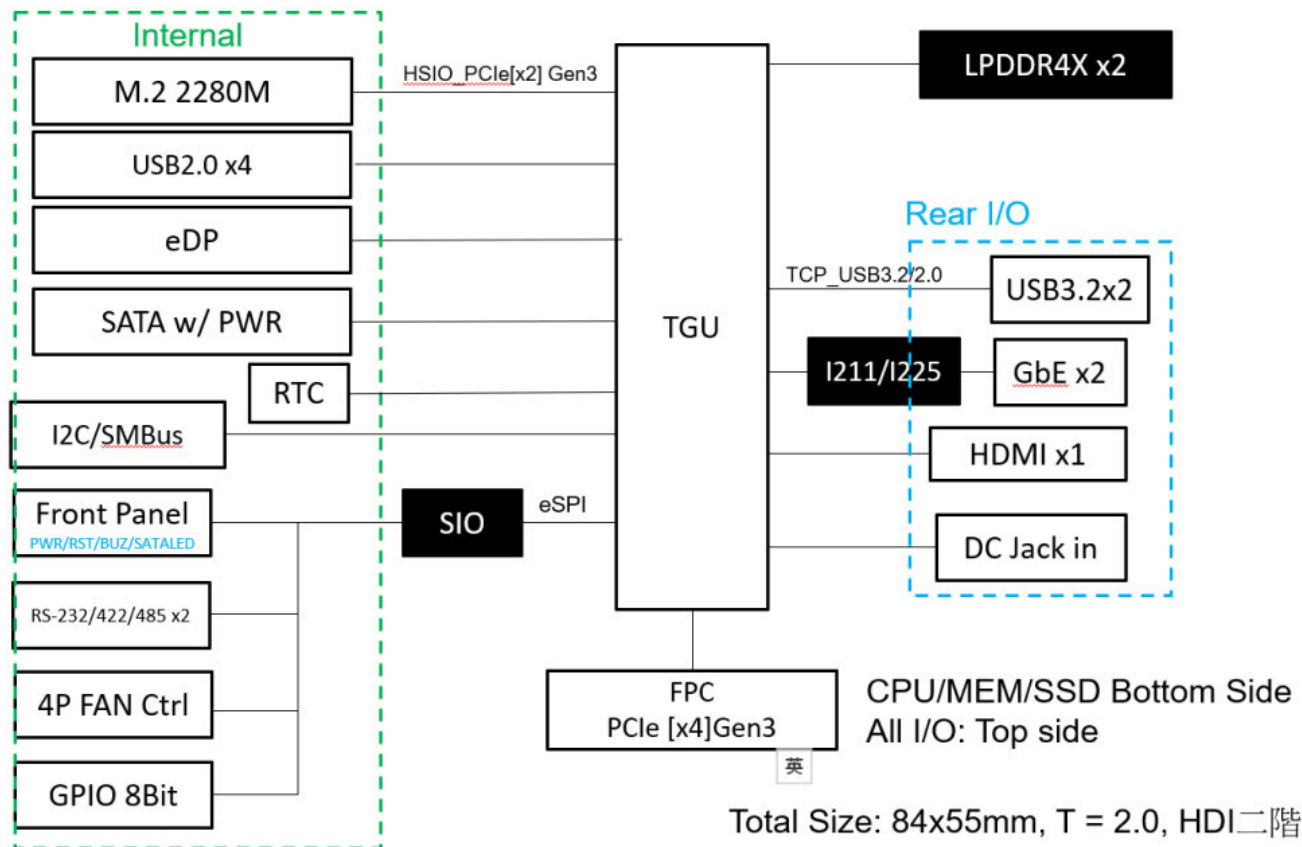


Project Name : DN-TGU8

Project Number:

Version: A0.3_0_0



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2	System Setting
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5	SoC DDI
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11	SoC CNVi
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20	HDMI
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26	Super I/O
27	RS232-422-485 / DIO / USB2.0
28	FAN/BIOS/ eSPI/ HW Monitor
29	DC IN/MISC
30	PWR_+V5A/ +V3P3A
31	PWR_+VDDQ_MEM/+VDDQ_LP4X_M
32	PWR_IMVP9 Controller
33	PWR_+VCCCORE
34	PWR_+VCCIN_AUX/+V1P8A
35	PWR_+VCCST_CPU/+VCCSTG_CPU
36	PWR_+V12S/ +V5S/ +V3P3S
37	Revision History

<Variant Name>

AAEON Technology INC.			
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SoC GPIO Pins :

Name	Power Well	Default	GPIO Function	Location
GPP_A14/USB_OC1#/DDSP_HP03/I2S3_RXD/DISP_MISC3/DMIC_CLK_B1	+V3P3S	PD	DDI3_HP0	DH52
GPP_A15/USB_OC2#/DDSP_HP04/DISP_MISC4/I2S4_SCLK	+V3P3S	PD	DDI4_HP0	DK45
GPP_E4/DEVSLP0	+V3P3A	PU	USB2_OC2#	DG8
GPP_E5/DEVSLP1	+V3P3A	PU	USB2_OC1#	DN6
GPP_E3/CPU_GP0	+V3P3A	PU	SMI#	DU5
GPP_E7/CPU_GP1	+V3P3A	PU	SCI#	DF8
GPP_T2	+V3P3A	PD	BOARD_ID1	D135
GPP_T3	+V3P3A	PD	BOARD_ID0	DN33
GPP_U4	+V3P3A	PD	BOARD_ID3	DG19
GPP_U5	+V3P3A	PD	BOARD_ID2	DG17
GPP_B23/SML1ALERT#/PCHHOT#/GSP1I_CS1#	+V3P3A	PU	ESPI_ALT#	CY50
GPP_H19/TIME_SYNC0	+V3P3S	PU	EC_KBRST#	DJ27

EC GPIO Pins :

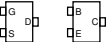
Name	Power Well	Default	GPIO Function	Location	Note
KS11/AFD#	+V3P3A	Input	I_RSMRST	J13	
RING#/PWRFAIL#/CK32KOUT/LPCRST#/GPB7	+V3P3A	Output	O_RSMRST	A1	When J13 active HIGH, then PU A1 after 10ms
KSO5/PD5	+V3P3A	Output	ESPI_EN#	J8	PU to Enable COM eSPI out
L80HLAT/BAO/WUI24/GPE0	+V3P3A	Input	GPI0	N2	
EGAD/WUI25/GPE1	+V3P3A	Input	GPI1	A13	
EGCSa/WUI26/GPE2	+V3P3A	Input	GPI2	A12	
EGCLK/WUI27/GPE3	+V3P3A	Input	GPI3	B12	
HSCe#/GPH3/ID3	+V3P3A	Output	GPO0	A9	
HSCk/GPH4/ID4	+V3P3A	Output	GPO1	B8	
HMISO/GPH5/ID5	+V3P3A	Output	GPO2	A8	
HMOSI/GPH6/ID6	+V3P3A	Output	GPO3	B7	

SMBus/I2C Addresses :

Device	address
I219	0XC8
PTN3460BS/F6	0C0h

PCB Footprints

MOSFET BJT



PCB STACK :

Board: TU883
Impedence: 50ohm +/-10%
Thickness: 2.0mm +/-10%

- Layer 1 : Component (Top)
- Layer 2 : GND (GND1)
- Layer 3 : Signal (IN1)
- Layer 4 : GND (GND2)
- Layer 5 : Signal (IN2)
- Layer 6 : GND (GND3)
- Layer 7 : Signal (IN3)
- Layer 8 : POWER (VCC)
- Layer 9 : POWER (VCC)
- Layer 10 : Signal (IN4)
- Layer 11 : GND (GND4)
- Layer 12 : Signal (IN5)
- Layer 13 : GND (GND5)
- Layer 14 : Signal (IN6)
- Layer 15 : GND (GND6)
- Layer 16 : Solder (Bottom)

<Variant Name>

AAEON Technology INC.			
Title		System Setting	
Size	Document Number	Rev	
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Power Delivery

Example:

Enable

Solution IC

Function

Power Good

PM_SLP_S3#

NCP45520IMNTWG

Power Load Switch

V12S_PG

+V12S@3A

0.5A

FAN

1.5A

eDP Backlight

1A

PCIE_FPC

I ALL SYS PWRGD

IMVP9(TBD)

DC/DC Buck

VR_RDY

+VCCCORE@66A

(+2V)

+VDDQ_VPP_PG

PM_SLP_S4#

NB685GQ-Z

DC/DC Buck

VDDQ_PG

+VDDQ@9.9A

(+1.1V)

+VIN

TPS53219ARGTR

DC/DC Buck

V5IN_PG

+V5A

@9.011A

0.062A

PM_SLP_S4# /VDDQ_PG

NB685GQ-Z

DC/DC Buck

VDDQ_TX_PG

+VDDQ_LP4X_MEM@0.52A

(+0.6V)

8.4A

+VDDQ

0.52A

+VDDQ_MEM

1A

+V1.8U_MEM

16GB LPDDR4X CHA

MEMORY DOWN

4A

USB 3.1*2 Real (2A)

USB 2.0*4 (2A)

PM_SLP_SUS#

SY8859GWC

DC/DC Buck

V1P8A_PG

+V1P8A

@2.635A

1A

PM_SLP_S4#

NCP81269MNTWG

Power Load Switch

VDDQ_VPP_PG

+V1.8V

+V1.8U_MEM@1A

1.635A

V12S_PG

NCP45520IMNTWG-H

Power Load Switch

V5S_PG

+V5S

@4A

0.5A

HDMI CONNECTOR

2A

SATA CONNECTOR

0.5A

DIO

1A

RS232*2

V1P8A_PG

NCP81269MNTWG

Power Load Switch

VCCIN_AUX@27A

(0V~+1.8V)

V5IN_PG

SY8288ARAC

DC/DC Buck

V3P3A_PG

+V3P3A

@5.62A

0.213A

V5S_PG

NCP45520IMNTWG-H

Power Load Switch

V3P3S_PG

+V3P3S@4A

2.5A

M.2 2280 KEY M

1A

eDP VDD

0.5A

PCIE FPC

LAN I219

0.74A

LAN I225

0.67A

Tiger Lake-U CPU

VCCIN

VDD2(LPDDR4/MEMORY DOWN)

VCCSTG_OUT

+VCCSTG_CPU@0.3A

VCCSTG_1-2

VCCST

+VCCSTG_CPU@0.5A

(+1.025V)

+VCCSTG_CPU@0.3A

(+1.025V)

VCCSTG_3-5

Tiger Lake-U PCH

VCCA_CLKLDO_1P8

VCCPRIM_1P8

VCC_VNNEXT_1P05

(VNN_BYPASS)

VCC_V1P05EXT_1P05

(V1P05_BYPASS)

VCCRTC

VCC1P05_OUT_FET

(Used for CPU rails VCCST/STG)

Vccin_AUX

VCCPRIM_3P3

VCCDSW_3P3

VCCPGPPR(3.3V or 1.8V)

VCCLDOSTD_0P85

(This rail is generated internally)

VCCDSW_1P05

(This rail is generated internally)

VCCPRIM1P05_OUT_PCH

(for CNVI and other internal I/O blocks)

(Not Used)

VCCDPHY_1P24

(This rail is generated internally with a LDO for 1.24 V for CNVI logi)

Figure 263. VCCST Enable Logic of PDG

VCCIN_AUX_CORE_VID0 "OR"
VCCIN_AUX_CORE_VID1 "OR"
VCCST_OVRD "OR"
PM_SLP_S3#

NCP45520IMNTWG-H

Power Load Switch

+VCC1P05_OUT_FET

+VCCSTG_OUT_1

+VCCSTG_CPU@0.5A

(+1.025V)

+VCCSTG_CPU@0.3A

(+1.025V)

Battery

3V

+VCC1P05_OUT_FET

(+1.8V)

+VCCIN_AUX@27A

0.09A

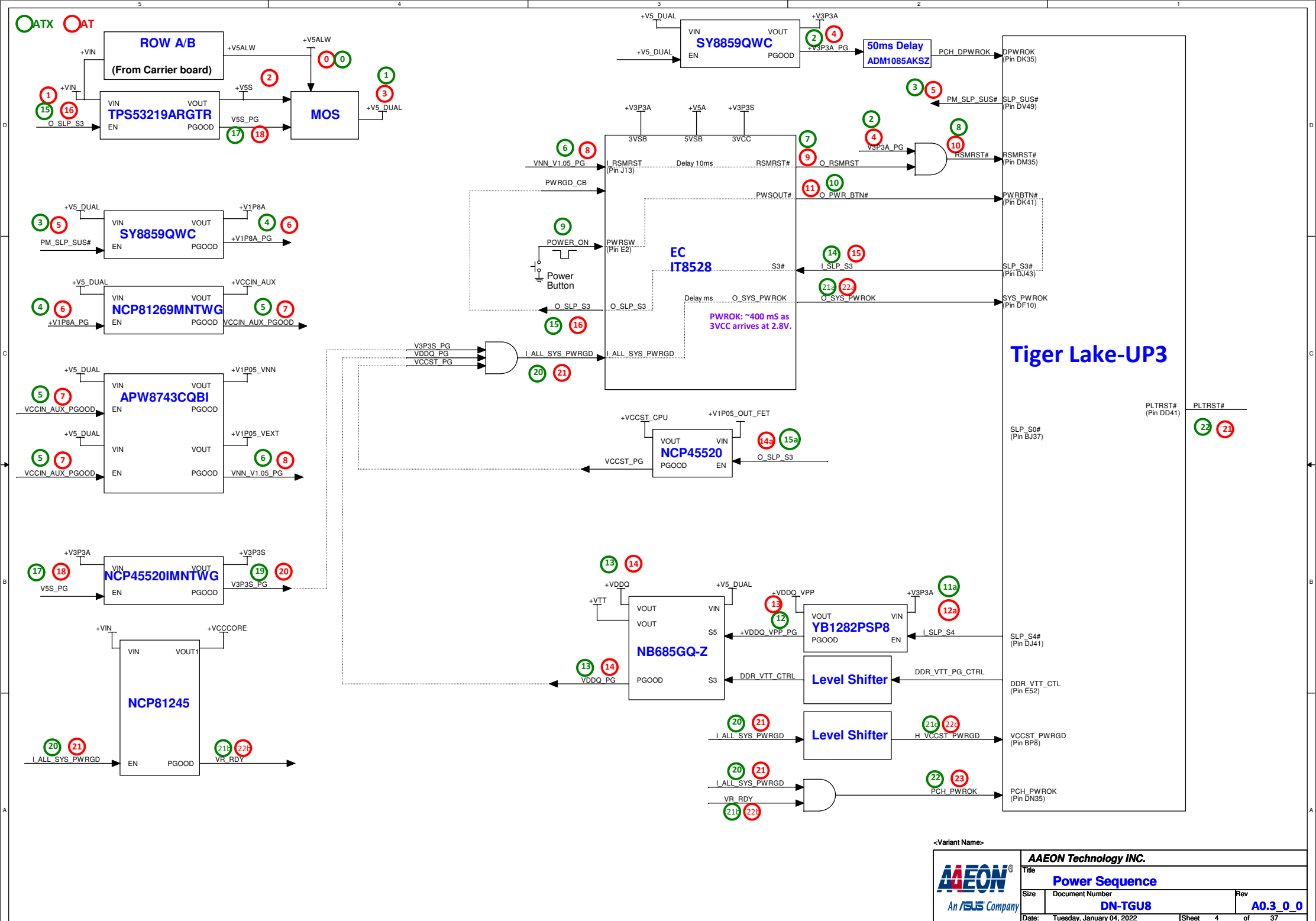
1.545A

0.339mA

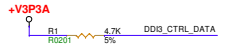
0.186A

0.005A

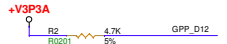
0.022A



The internal pull-down 20k is disabled after RSMRST# de-asserts.



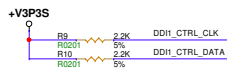
The internal pull-down 20k is disabled after RSMRST# de-asserts.



This strap has a 20 kohm \pm 30% internal pull-down.



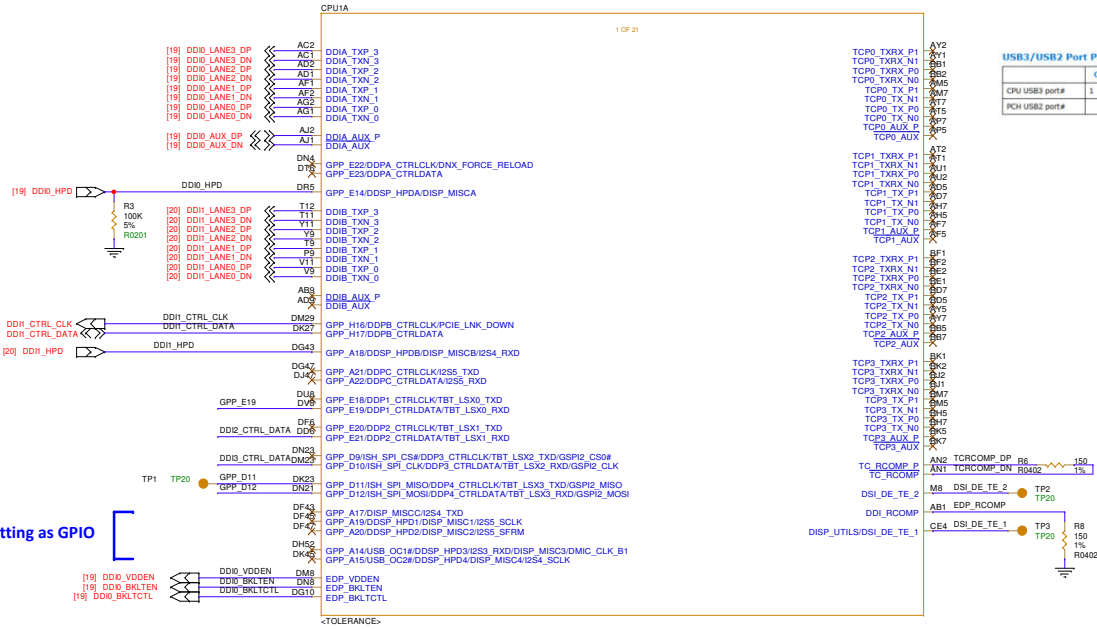
This strap has a 20 kohm \pm 30% internal pull-down



EDP

HDMI 1.65G

Setting as GPIO



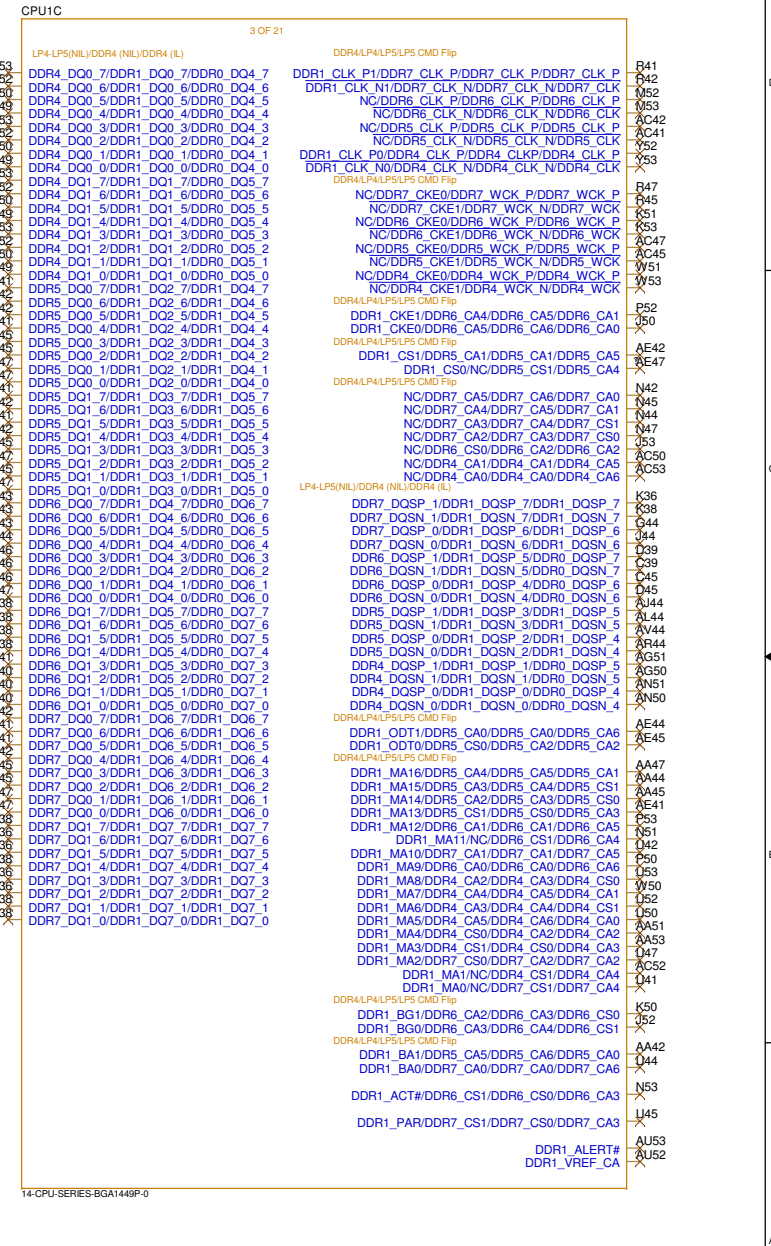
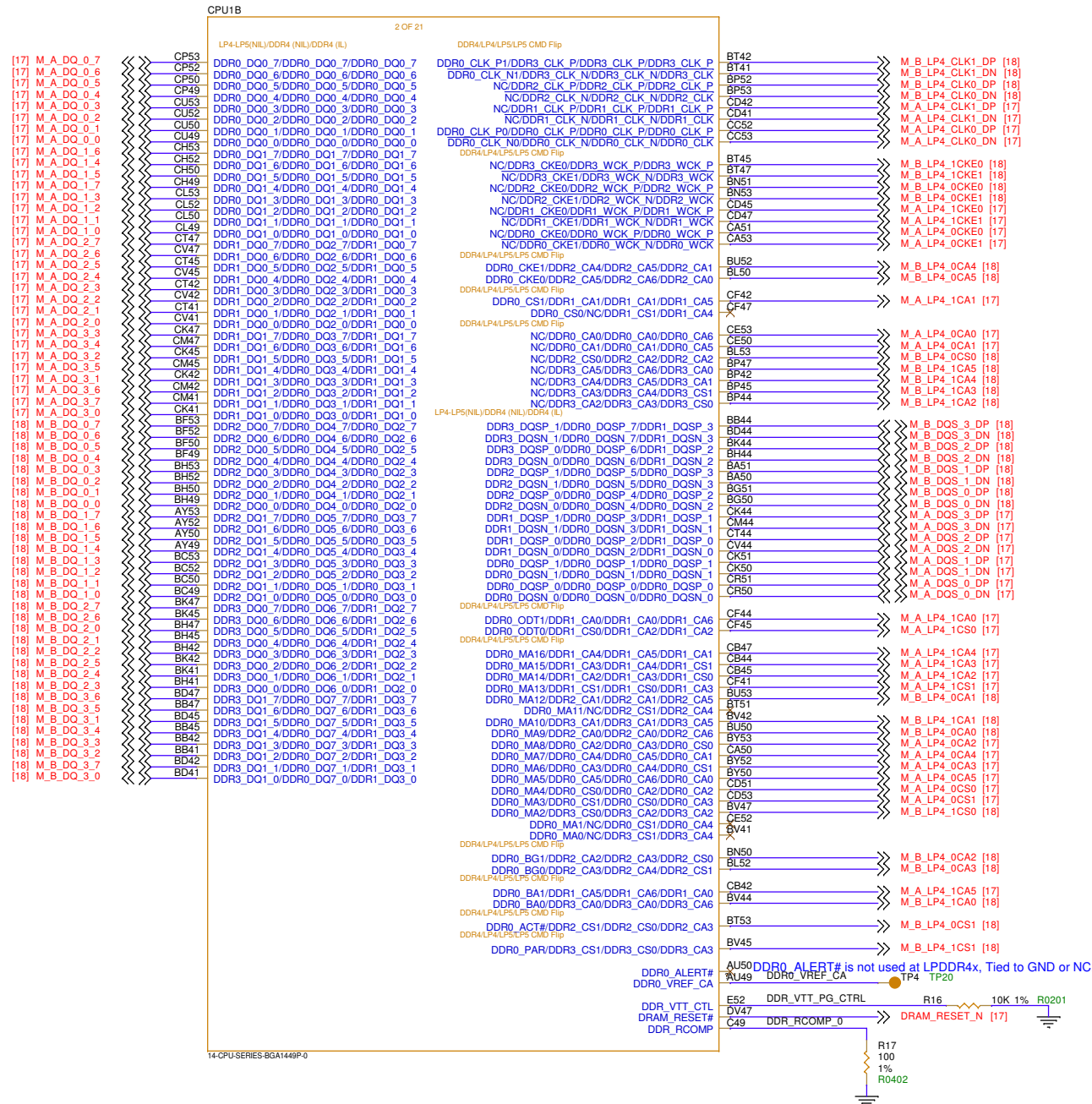
USB3/USB2 Port Pairing for USB-C® Connectors

	Connector C0	Connector C1	Connector C2	Connector C3
CPU USB3 port#	1	2	3	4
PCH USB2 port#	2	3	4	5

20210519, A02, Change USB3.2 Port 1/2 from TCP to PCH HSIO.

USB 3.2 PORT 1/2

SoC LPDDR4x x32



<Variant Name>

**AAEON Technology INC.**

SoC LPDDR4x

Size	Document Number
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	DN-TGU8
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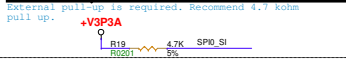
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[illegible]

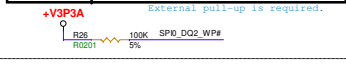
Rev

3	A0.3_0_0
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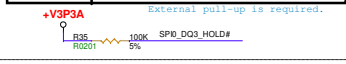
SPIO_MOSI	Reserved
External pull-up is required. Recommend 4.7 kohm pull-up. This strap should sample HIGH. There should NOT be any on-board device driving it to opposite direction during strap sampling.	



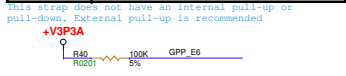
SPIO_IO2	Reserved
External pull-up is required. Recommend 100K if pulled up to 3.3V or 75K if pulled up to 1.8V. This strap should sample HIGH. There should NOT be any on-board device driving it to opposite direction during strap sampling.	



SPIO_IO3	Reserved
External pull-up is required. Recommend 100K if pulled up to 3.3V or 75K if pulled up to 1.8V. This strap should sample HIGH. There should NOT be any on-board device driving it to opposite direction during strap sampling.	



GPP_E6	JTAG ODT Disable
0	JTAG ODT is disabled
1 *	JTAG ODT is enabled



DBG_PMODE	Reserved
This strap should sample high. There should NOT be any on-board device driving it to opposite direction during strap sampling.	

This strap has a 20 kohm ± 30% internal pull-up.

GPP_H0	BFX STRAP 1- BIT 2
0010 = Master Attached Flash Configuration (BIOS / CSME on SPI). eSPI is disabled	



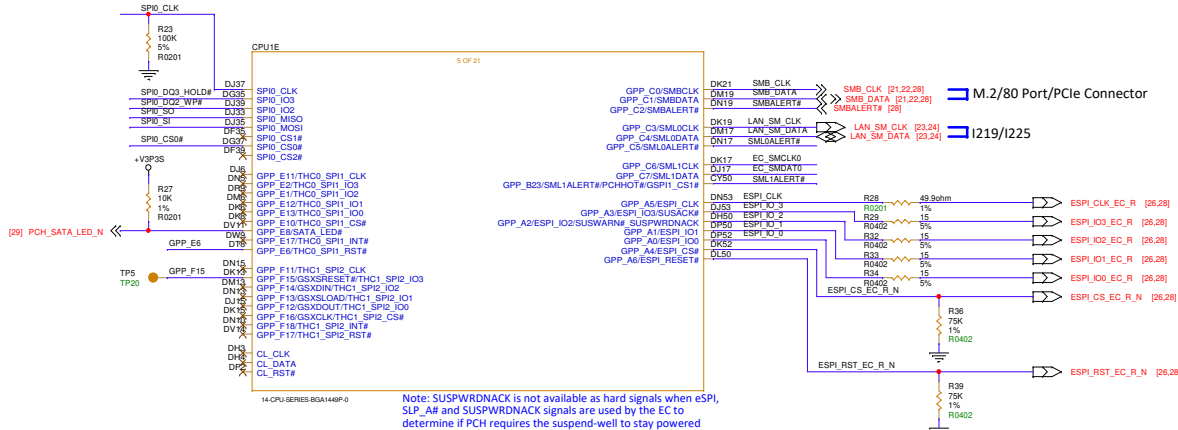
GPP_H1	BFX STRAP 2- BIT 3
This strap has a 20 kohm ± 30% internal pull-down.	



GPP_H2	BFX STRAP 3- BIT 4
This strap has a 20 kohm ± 30% internal pull-down.	



SoC SPI/LPC/SMBus



SoC HDA/SD

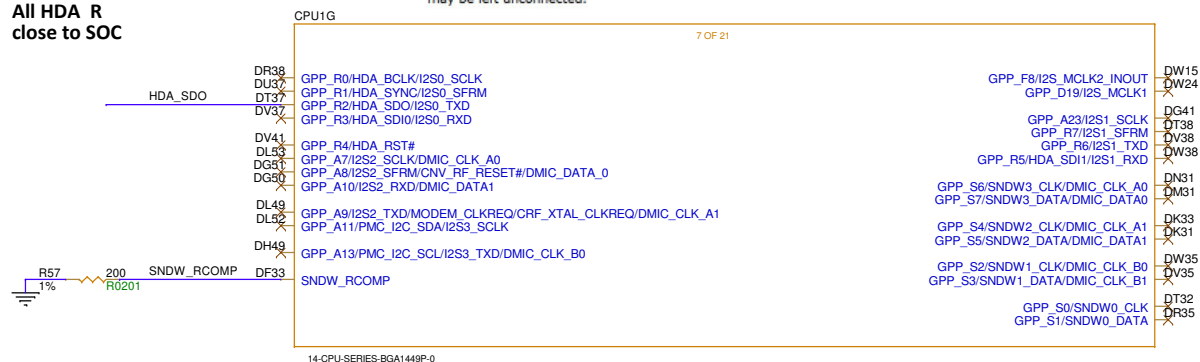
HDA_SDO	Flash Descriptor Security Override
0 *	Disabled (Default)
1	Enable (Disable ME)(debug ONLY)

* Default, Internal Pull-Down 20K



A02, 20210407, add R361 and remove TP13 for intel ME disable issue.

All HDA R
close to SOC



Disabling and Termination Guidelines for High Definition Audio Interface

When HDA_SDIN[1:0] interface is not implemented on the platform the signal pin(s) may be left unconnected.

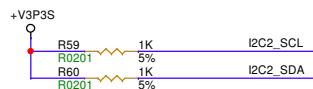
GSPI1_MOSI	No Reboot
0 *	REBOOT ENABLED
1	NO REBOOT

* Default, Internal Pull-Down 20K

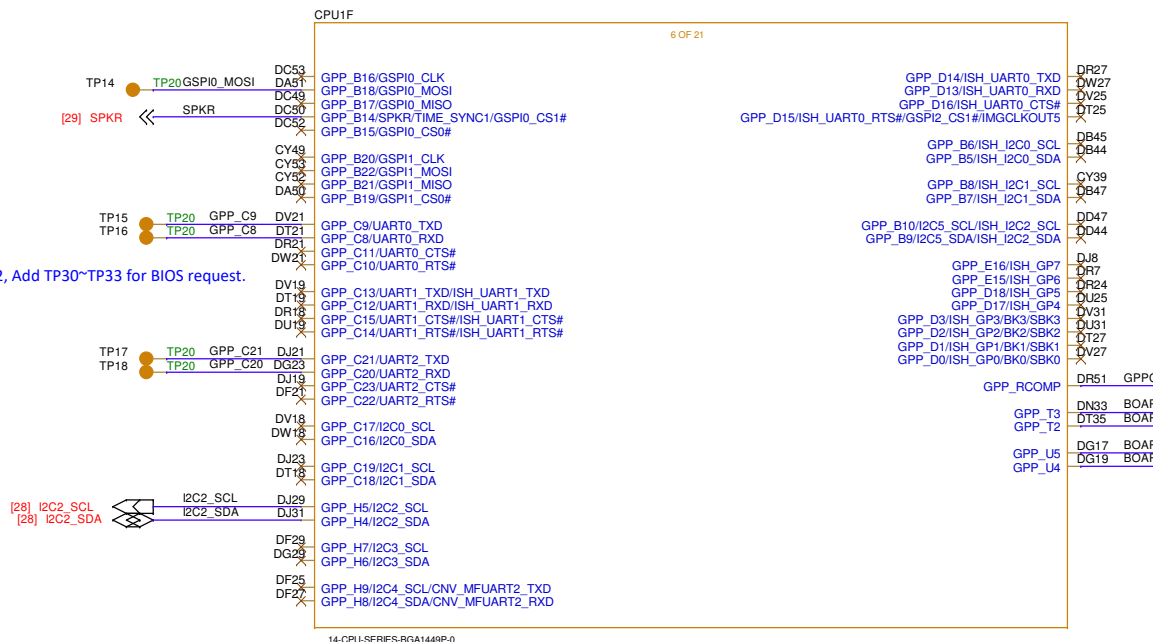
SPKR	Top Swap Override
0 *	Disabled
1	Enable

* Default, Internal Pull-Down 20K

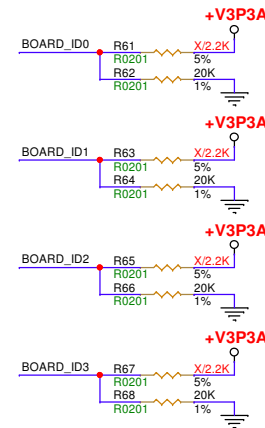
CRB: PULL UP 100K RESISTOR PRESENT ON THIS
NET



20200717, A02, Add TP30~TP33 for BIOS request.



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BOARD ID

Memory Down Select		
BID0	BID1	Memory Size

<Variant Name>

**AAEON Technology INC.**

Title **SoC HDA/I2C**

Size	Document Number DN-TGU8
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Rev	A0.3 0 0
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Date: Tuesday, January 04, 2022 Sheet 8 of 37

PCH PCIe/SATA/USB



PCIE FPC

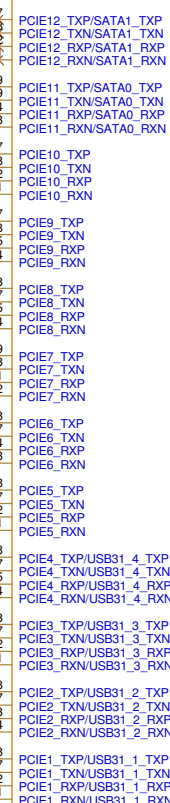
USB3.0 (Rear I/O)

20210519, A02, Change USB3 to PCH HSIO port 3/4

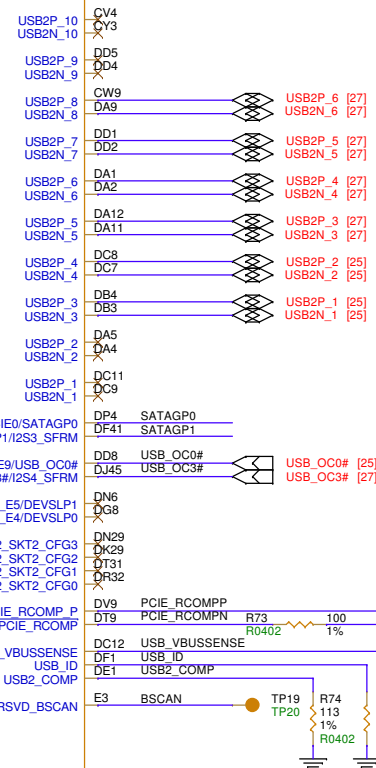
M.2 KEY M



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14-CPU-SERIES-BGA1449P-0

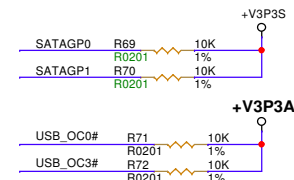


USB2.0 Header

USB3.0 (Rear I/O)

- USB3.0 (Rear I/O)

USB2.0 Header



USB3/USB2 Port Pairing for USB-C® Connectors

	Connector C0	Connector C1	Connector C2	Connector C3
CPU USB3 port#	1	2	3	4
PCIe USB2 port#	2	3	4	5

Figure 70. High Speed I/O (HSIO) Lane Multiplexing in PCH-LP (UP3)

Flex HSIOLane	HSIO Type and Lane										
0	USB 3.2 Gen 1x1/Zx1 #1	PCIe* #1									
1	USB 3.2 Gen 1x1/Zx1 #2	PCIe* #2									
2	USB 3.2 Gen 1x1/Zx1 #3	PCIe* #3									
3	USB 3.2 Gen 1x1/Zx1 #4	PCIe* #4									
4	PCIe* #5										
5	PCIe* #6										
6	PCIe* #7	GBE									
7	PCIe* #8	GBE									
8	PCIe* #9	GBE									
9	PCIe* #10										
10	PCIe* #11	SATA 0									
11	PCIe* #12	SATA 1									

<Variant Name>

AAEON Technology INC.

A4EON
An ASUS Company

Title	SoC PCIe/SATA/USB
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Size	Document Number
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DN-TGU8

Rev	A0.3 0 0
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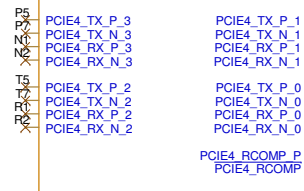
Date: Tuesday, January 04, 2022

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PROC PCIe

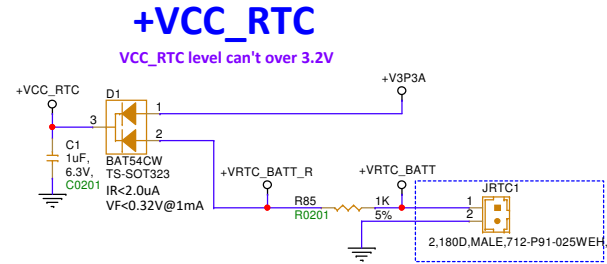
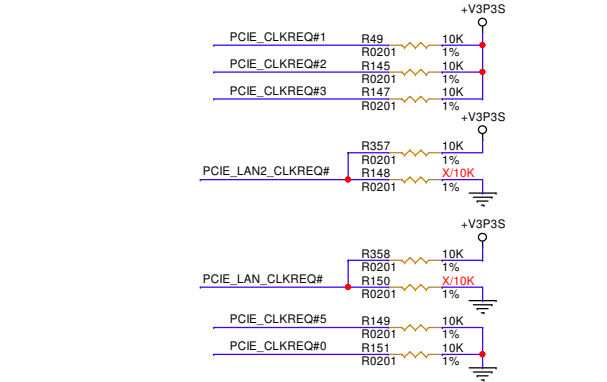
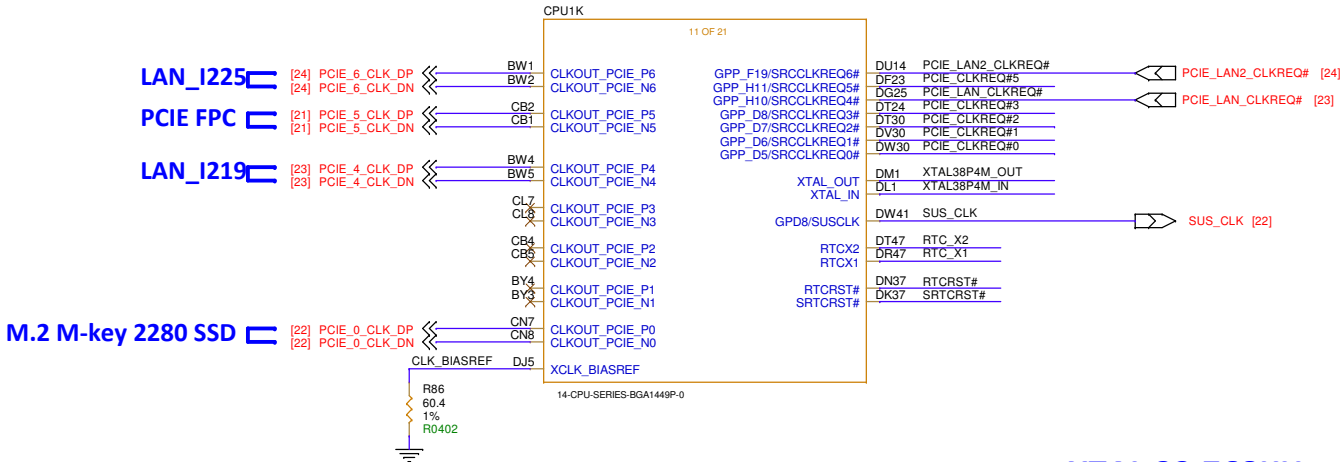


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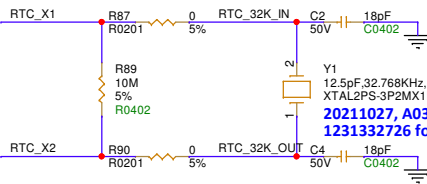
SoC PCIE_CLK/ RTC/ XTAL



20210831, A03, Change P/N of JRTC1 from 1655902034 to 1655X00019 by PE suggestion.
20220104, A03, Change Part's TYPE from DIP to SMD by PE request.

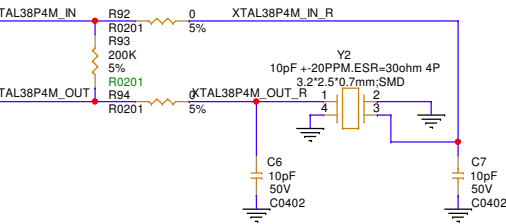


XTAL 32.768KHz

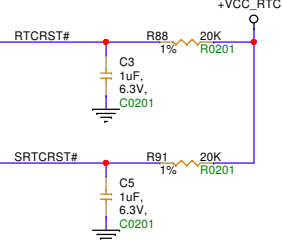


20211027, A03, Change P/N Y1 from 1231327631 to 1231332726 for change vendor

XTAL 38.4MHz



RTC_RESET

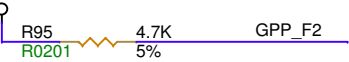


SoC CNVi

GPP_F2	M.2 CNVi Mode Select
0 *	Integrated CNVi enabled.
1	Integrated CNVi disabled.

This strap does not have an internal pull-up or pull-down. A weak external pull-up is required.

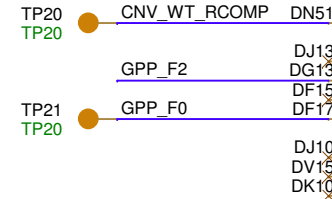
+V3P3A



GPP_F0	XTAL SEL1
0 *	38.4/19.2MHZ (DEFAULT)
1	24MHZ (25 MHZ WHEN XTAL FREQ DIVIDER NON ZERO)

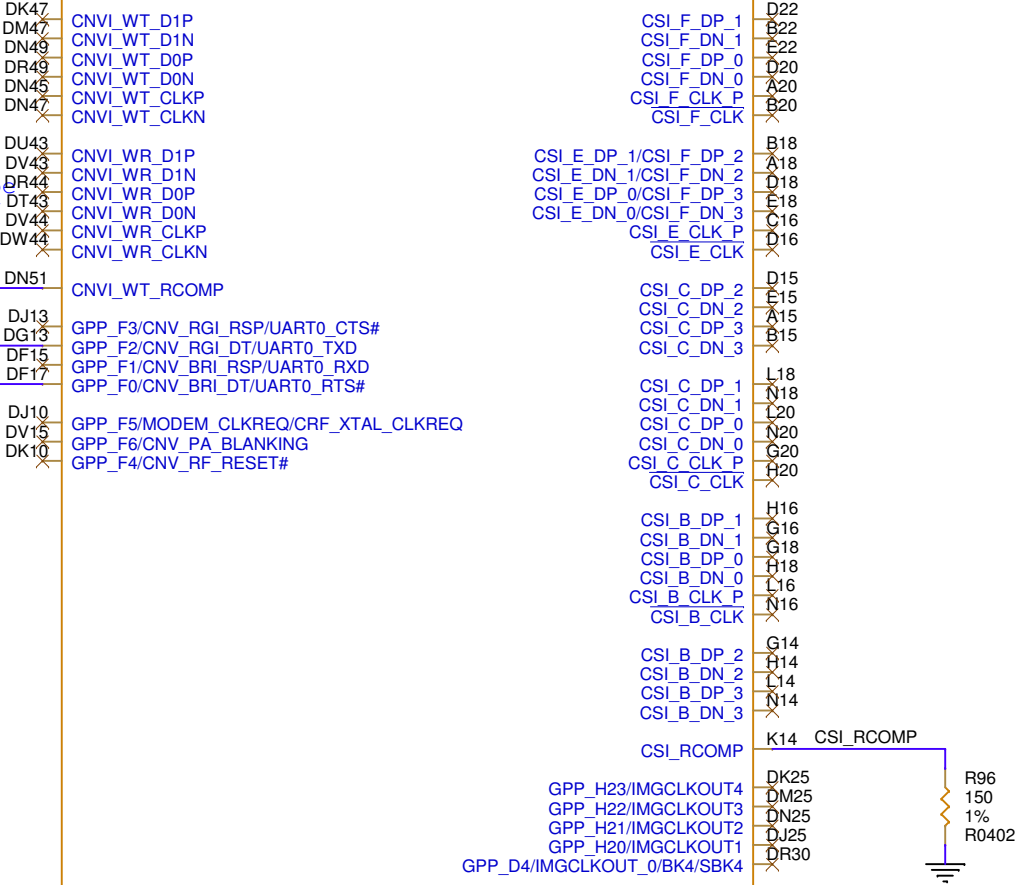
* Default, Internal Pull-Down 20k
24 MHz crystal is not supported

CNVI_WT_RCOMP can be left unconnected if not used.




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14-CPU-SERIES-BGA1449P-0

<Variant Name>



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An ASUS Company

AAEON Technology INC.

Title: **SoC CNVi**

Size: Document Number: **DN-TGU8**

Date: Tuesday, January 04, 2022

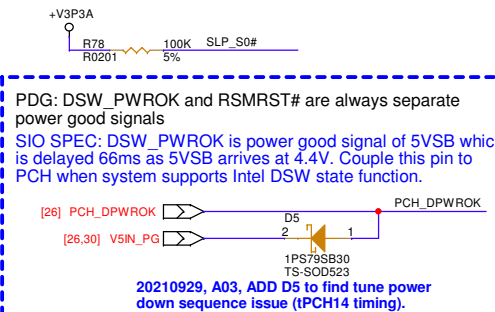
Rev: **A0.3_0_0**

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SoC System

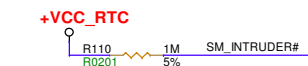
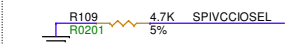
GPD7	Reserved
	This strap should sample LOW. There should NOT be any on-board device driving it to opposite direction during strap sampling.

This strap has a 20 kohm \pm 30% internal pull-down.



SP1VCCIOSEL	STRAP FOR SPI 1.8V/3.3V SELECTION
0 *	3.3 V
1	1.8 V

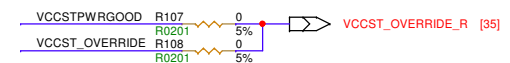
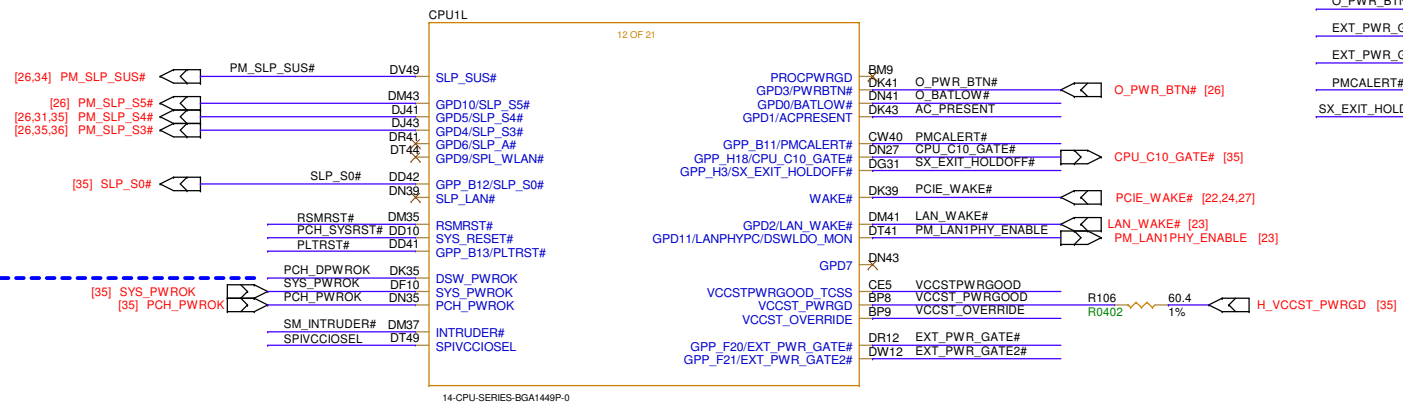
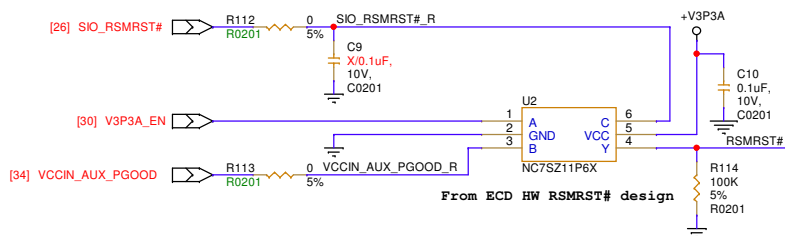
An external resistor is required.



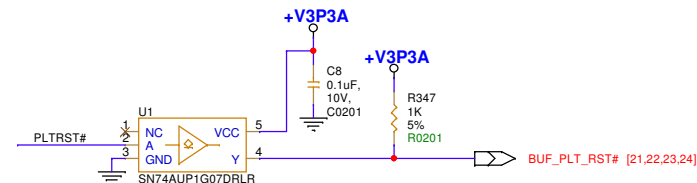
RSMRST# Control

NOTE:
PDG PAGE422, RSMRST# must always be driven low before any of the PRIMARY rails fall below the lower end of their tolerance band. This is true for all power states transitions including emergency power loss.

RSMRST# is power good signal of 3VSB, which is delayed 66ms as 3VSB arrives at 2.8V by SIO.



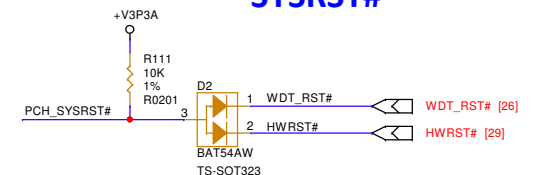
UAL BUFFER/DRIVER WITH OPEN-DRAIN OUTPUTS



- HDMI
- PCIE FPC
- M.2(Key E)
- M.2 M-key
- LAN-I219
- LAN-I211
- eSPI Connector

PCIE SSD

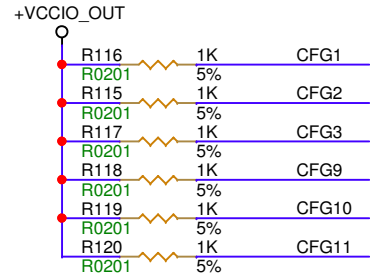
SYSRST#



SoC Strap

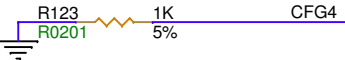
CFG14	PEG* Static x4 Lane Numbering Reversal
0	Lane numbers reversed
1 *	Normal operation

The CFG signals have a default value of '1'



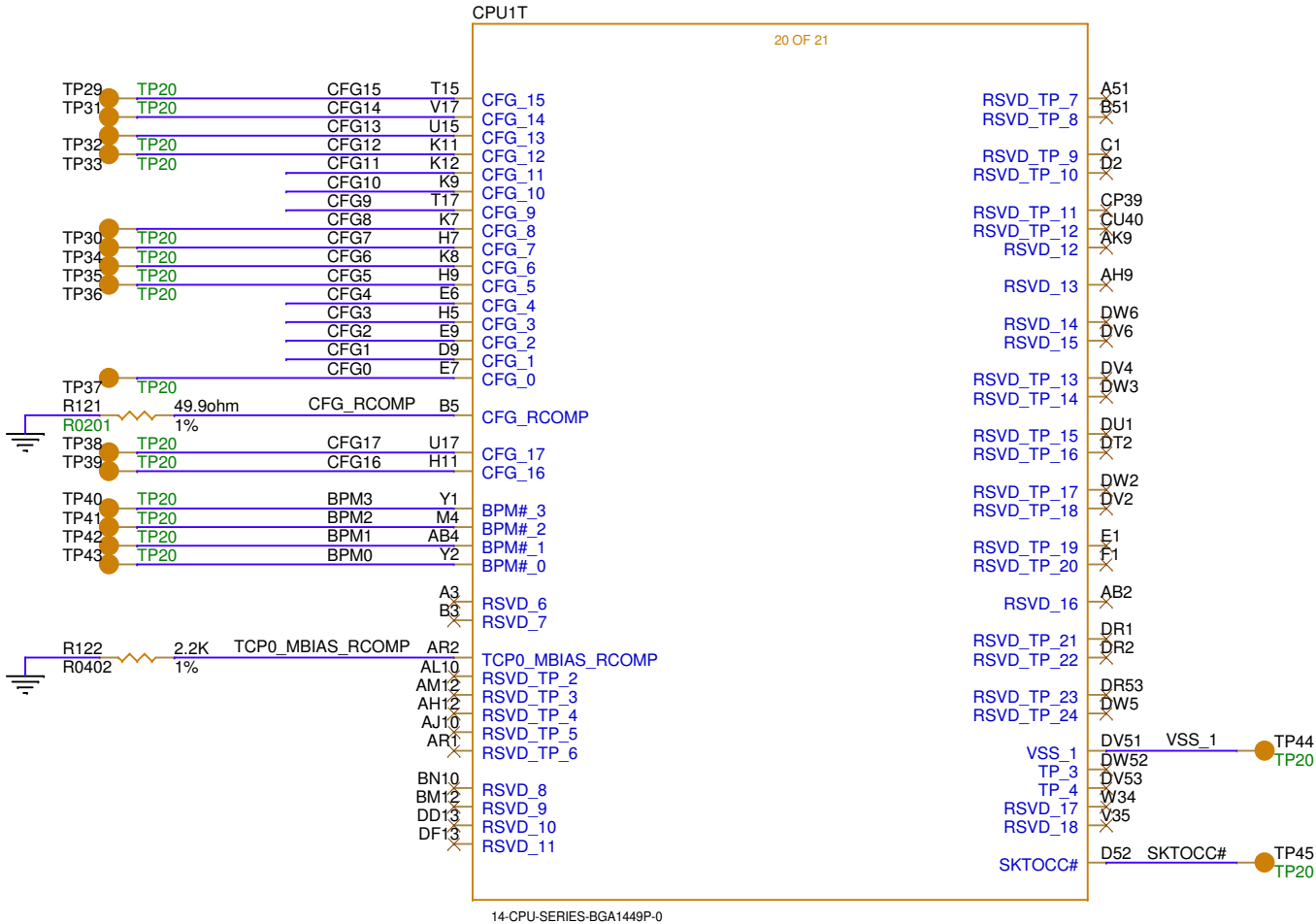
CFG4	eDP Presence
0 *	ENABLE
1	DISABLE

The CFG signals have a default value of '1'



CFG7	PEG Training
0	PEG Wait for BIOS for training
1 *	PEG Train immediately following RESET# de assertion

The CFG signals have a default value of '1'

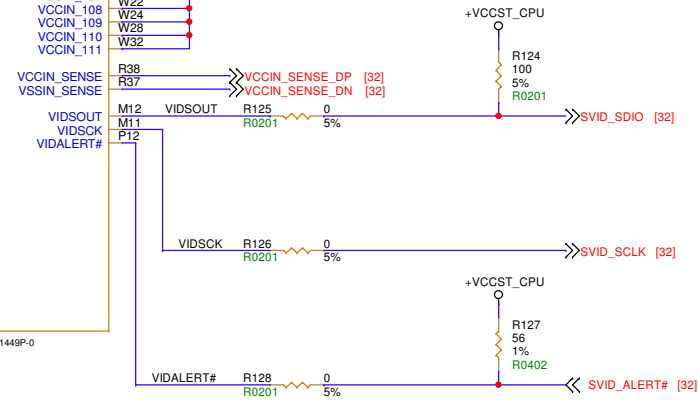
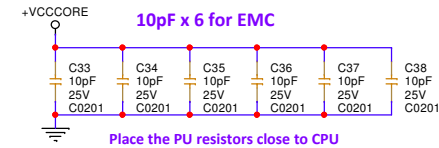


14-CPU-SERIES-BGA1449P-0

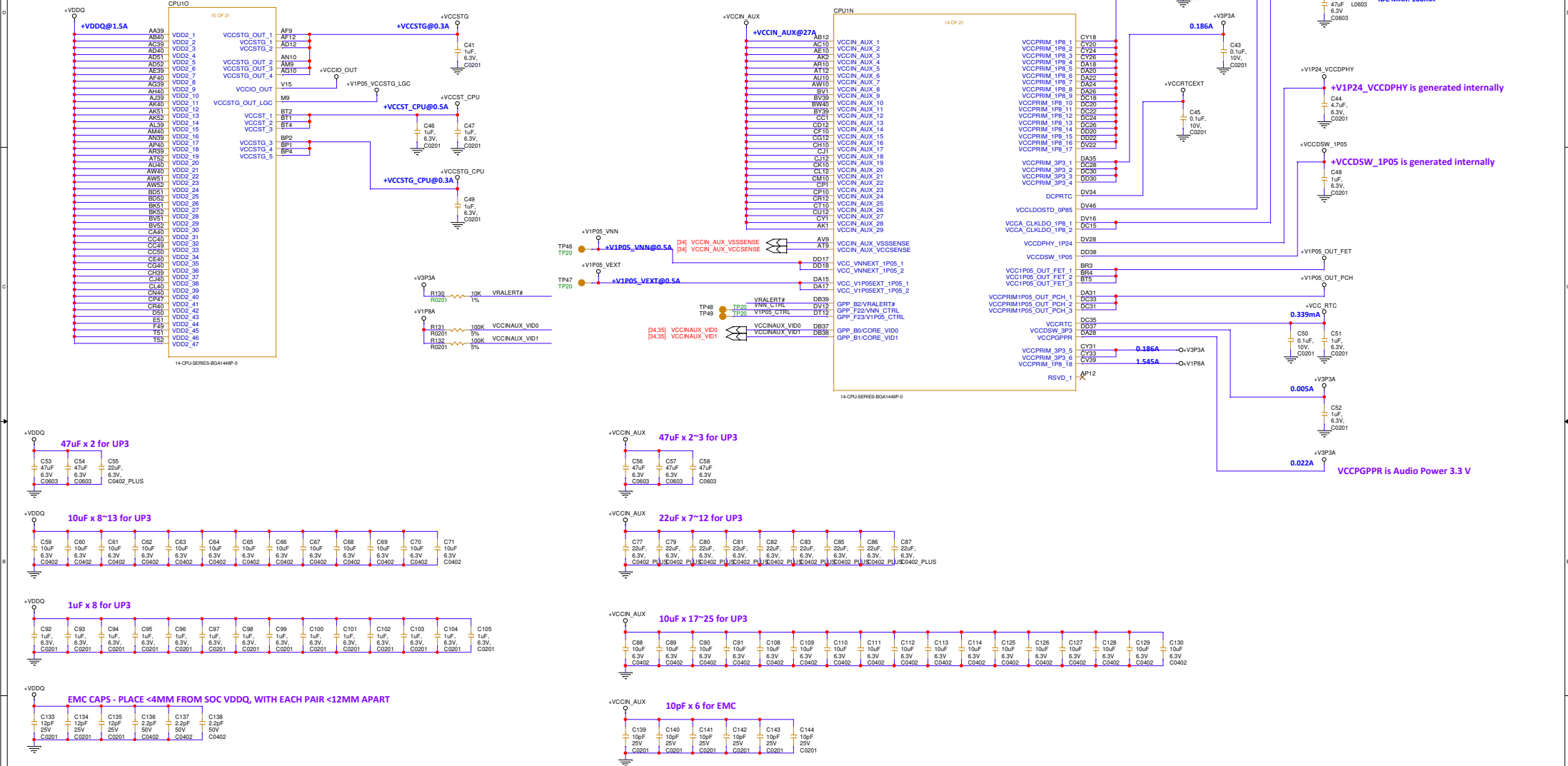
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AAEON Technology INC.			
Title SoC Strap			
Size A4	Document Number DN-TGU8		Rev A0.3_0_0
Date: Tuesday, January 04, 2022	Sheet 13	of 37	

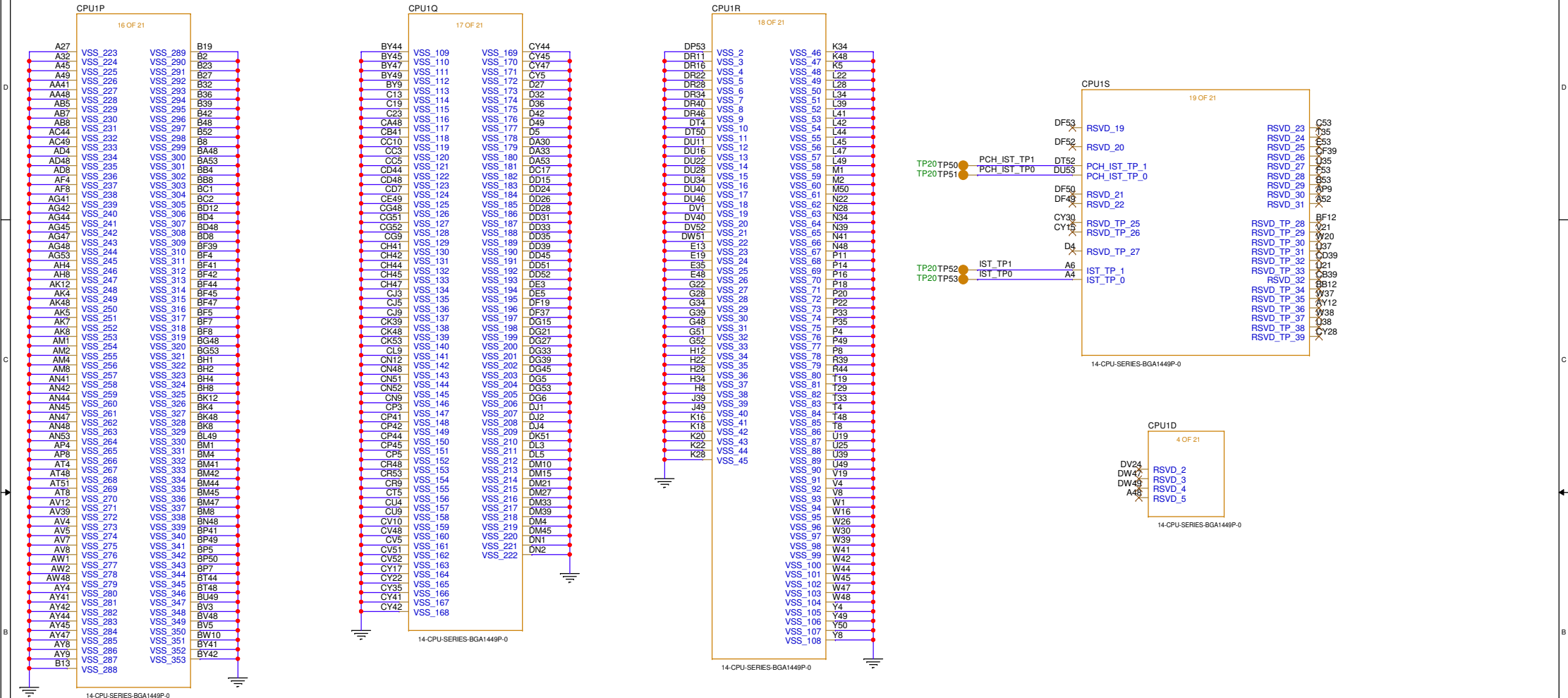
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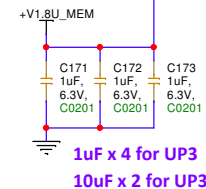
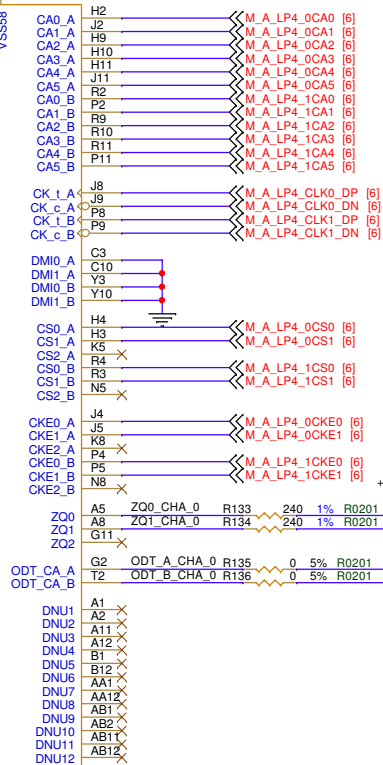
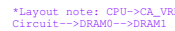
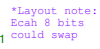
PCH Power

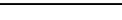


SoC GND



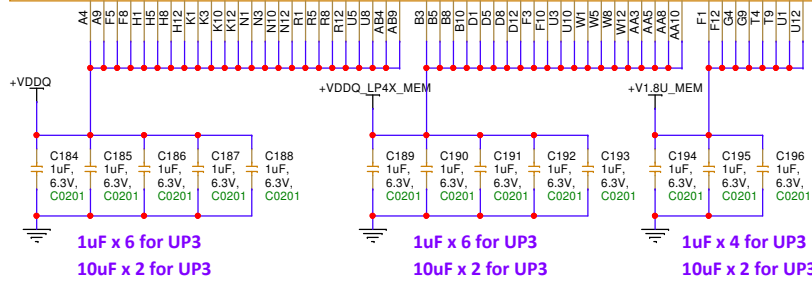
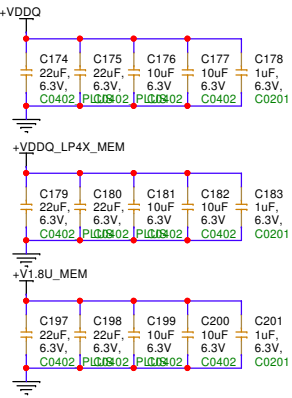
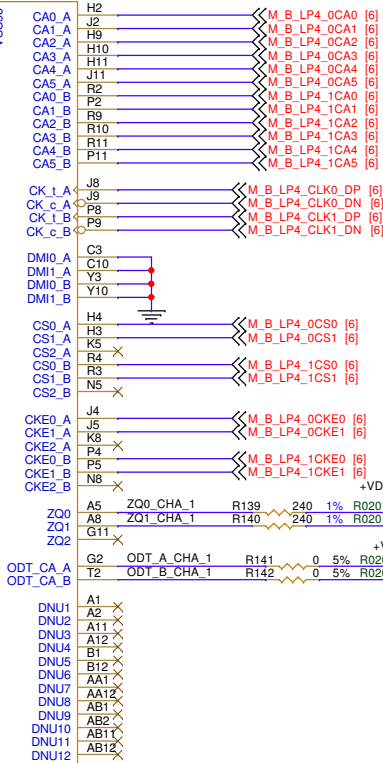
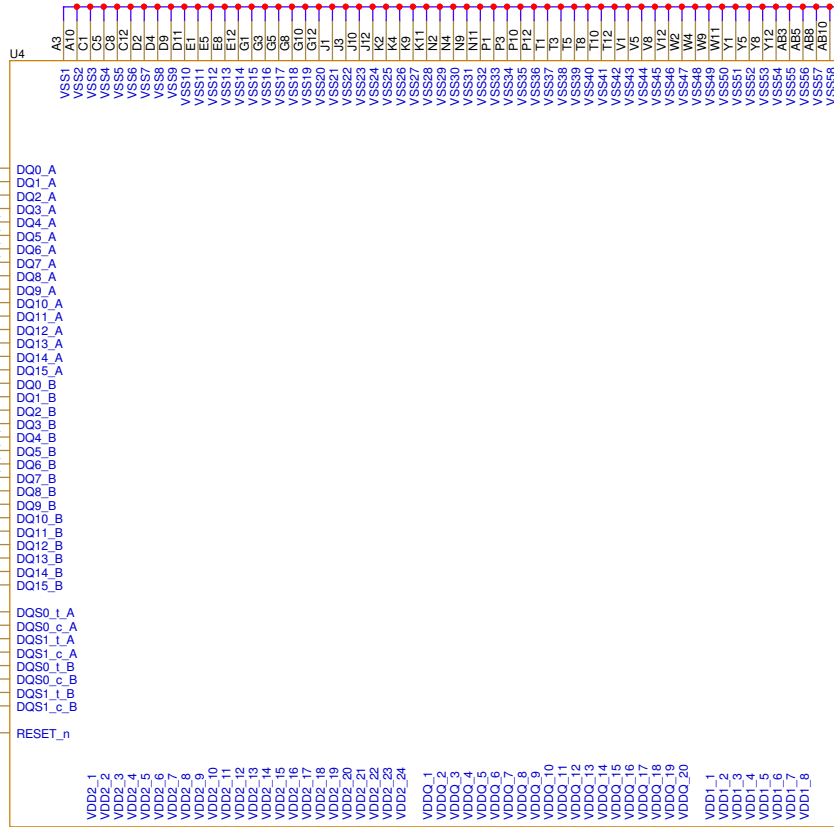
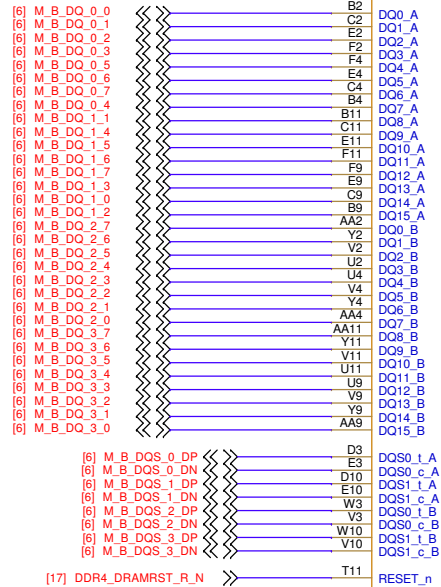
20201005 Run out of PCB space for DDR4 Memory down
Change design from DDR4 to 2*LPDDR4x



	AAEON Technology INC.		
	Title LPDDR4x (1/2)		
	Size A3	Document Number DN-TGU8	Rev A0.3_0_0
	Date: Tuesday, January 04, 2022		Sheet 17 of 37

LPDDR4x CHB

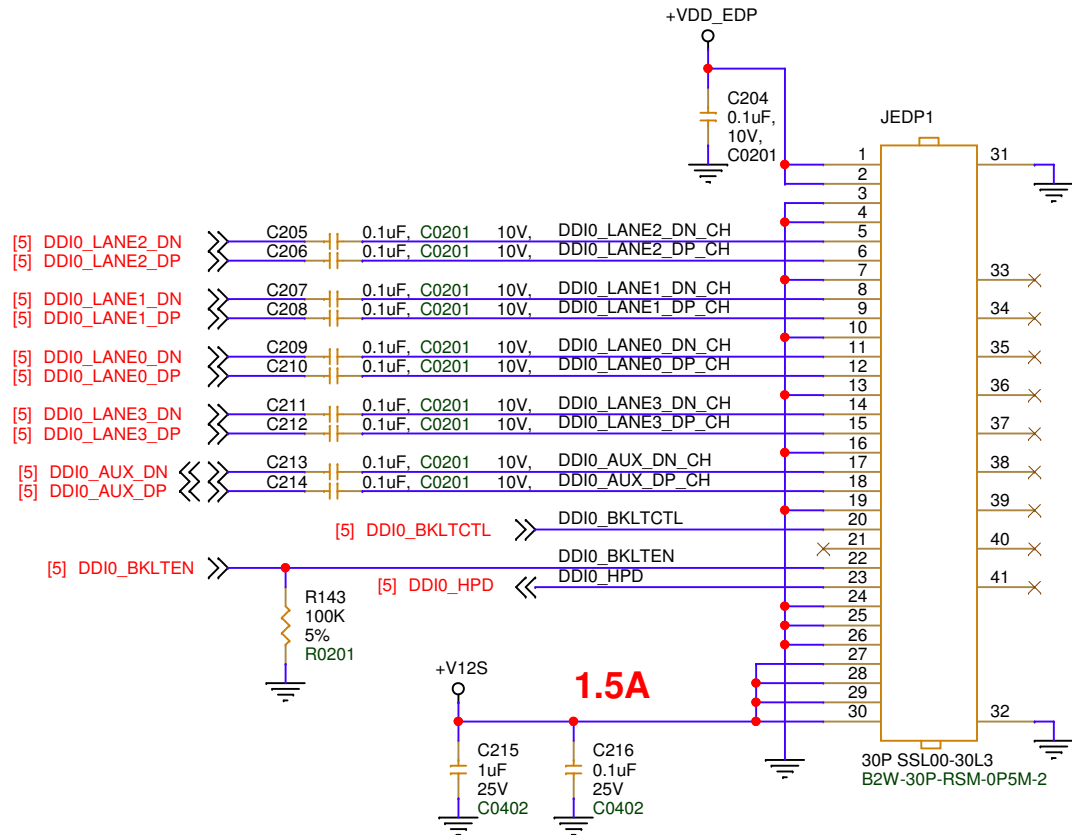
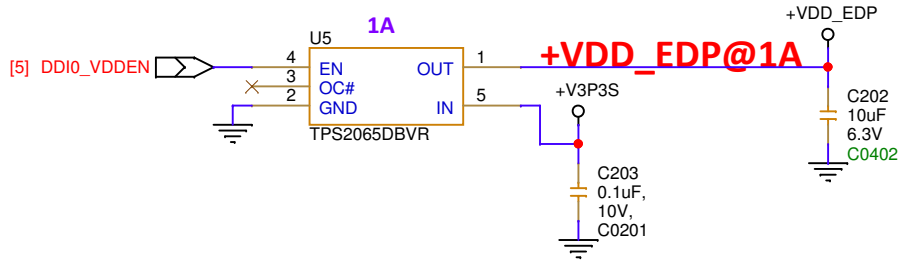
20201005 Run out of PCB space for DDR4 Memory down
Change design from DDR4 to 2*LPDDR4x



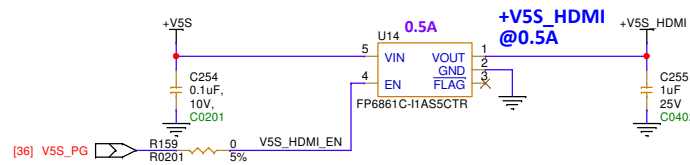
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eDP

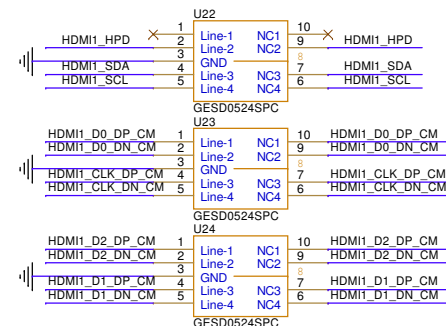
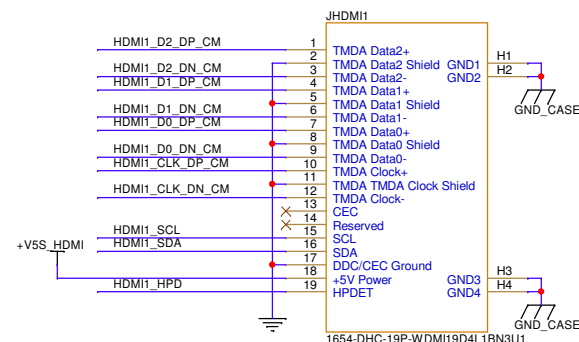
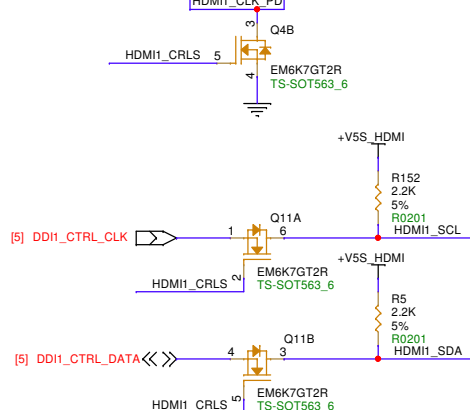
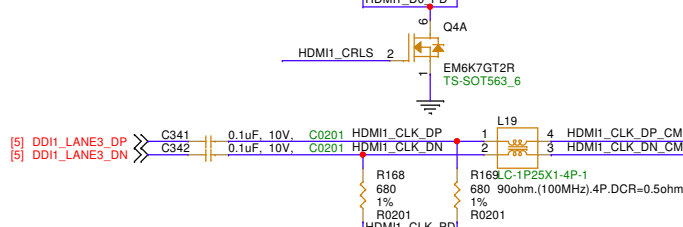
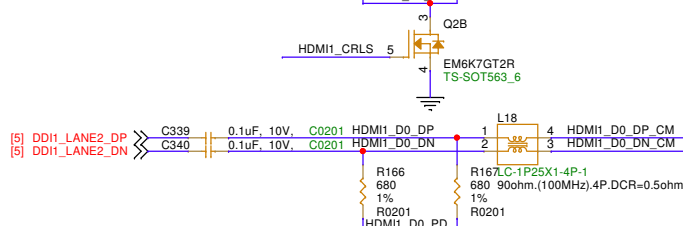
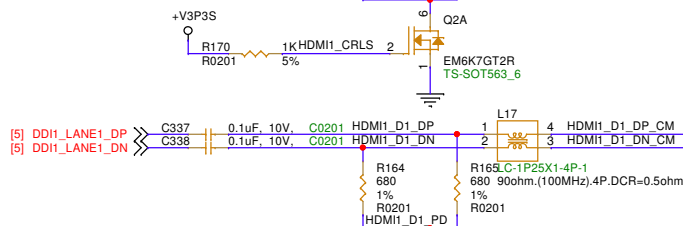
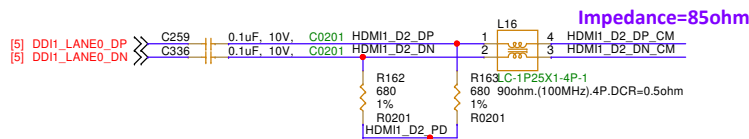
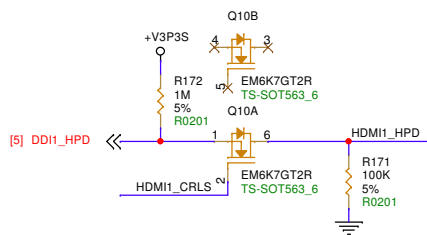
+VDD_EDP@1A



DDI1 to HDMI1



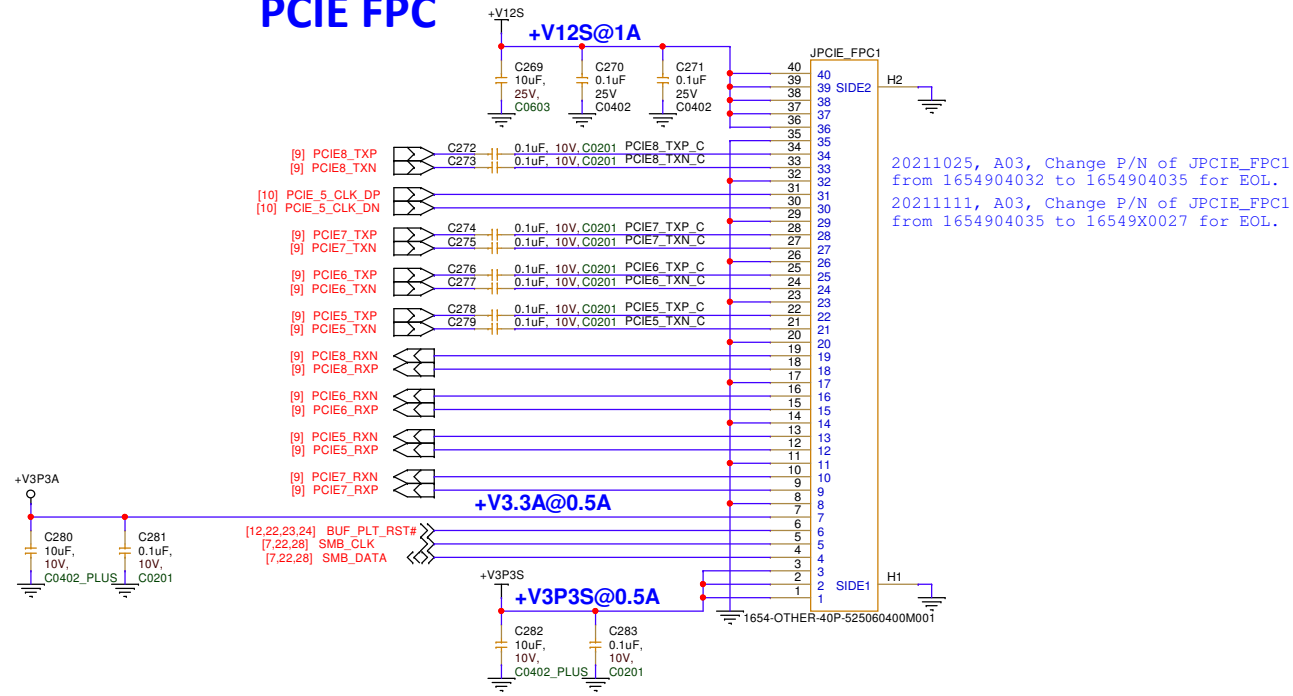
20210106, A01, Add V5S_PG for HW suggestion.



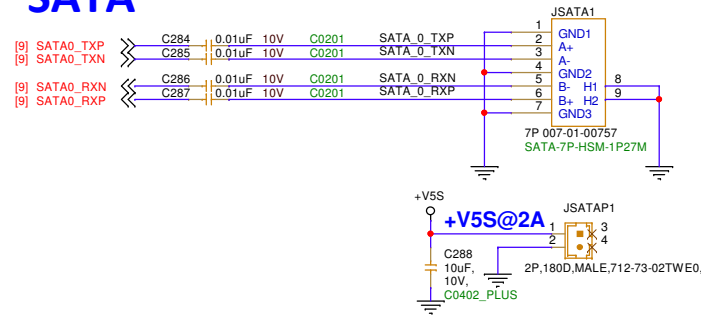
20211111, A03, U22~U24 EOL, Change P/N from 130505ESD0 to 1305Q00022

<Core Design>

PCIE FPC



SATA

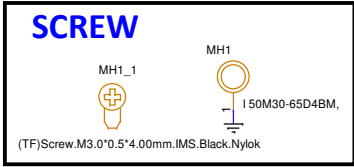
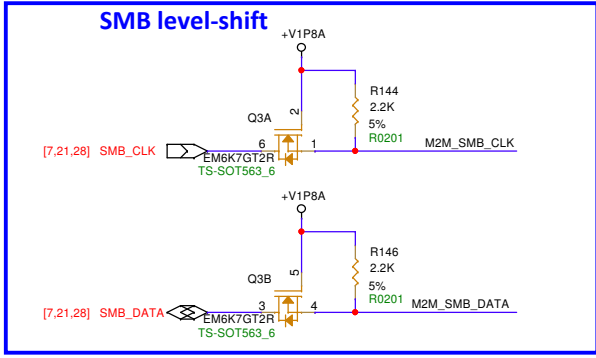
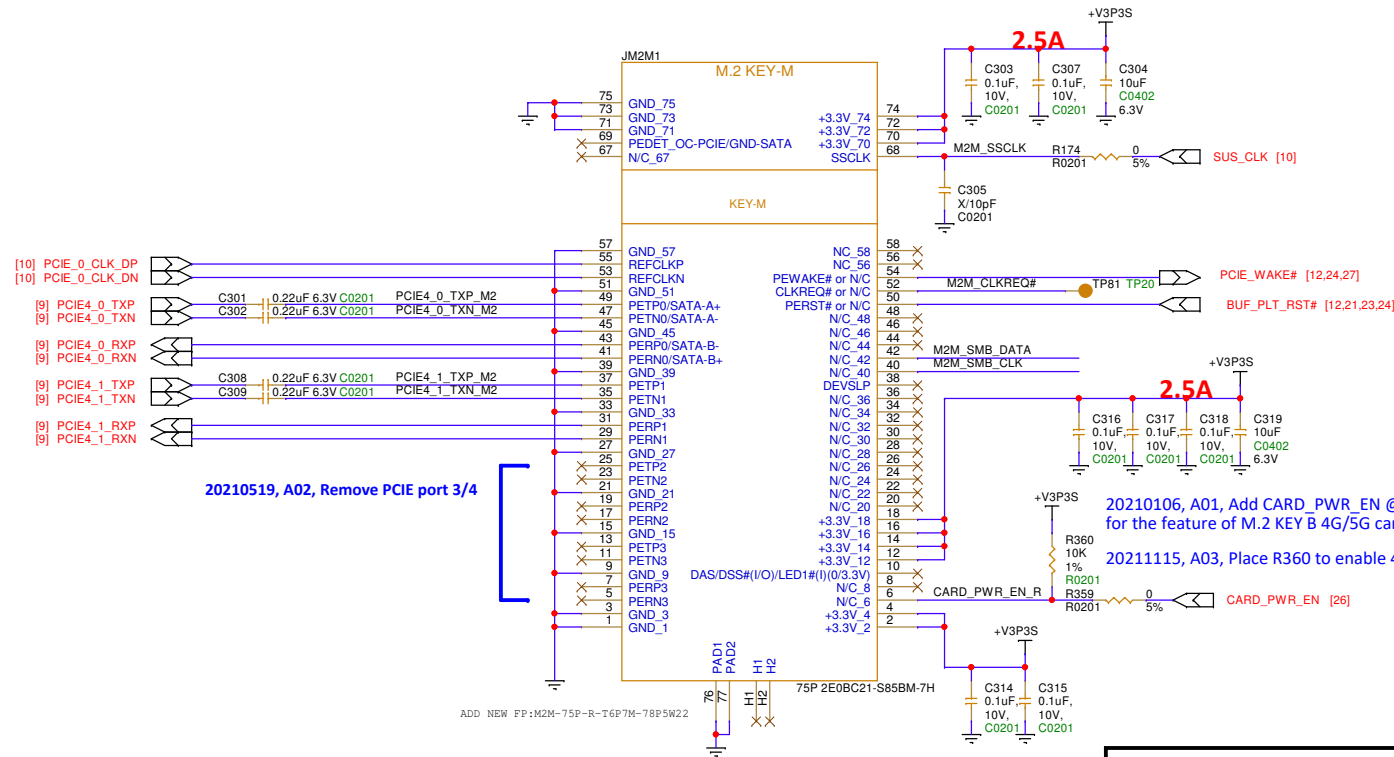


<Variant Name>



Title PCIE FPC/SATA		
Size A3	Document Number DN-TGU8	Rev: A0.3_0_0
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M.2 M-key 2280 SSD



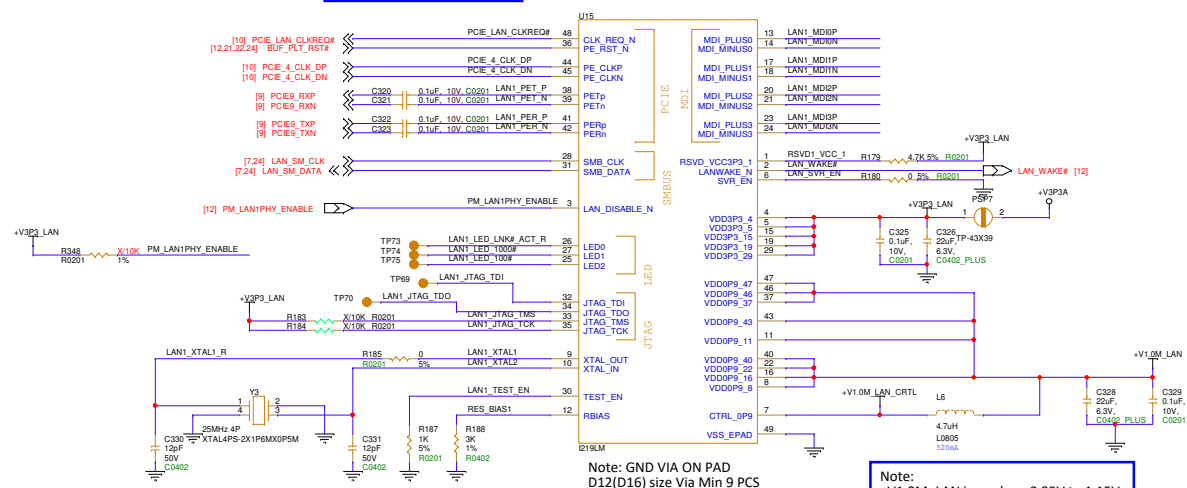
LAN-I219

ACTIVITY LED
Green = LINK UP
BLINKING = TX/RX ACTIVITY

SPEED LED
Off = Link 10 Mbps
Green = Link 100 Mbps
Orange = Link 1000 Mbps

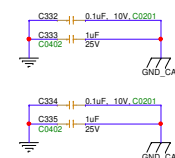
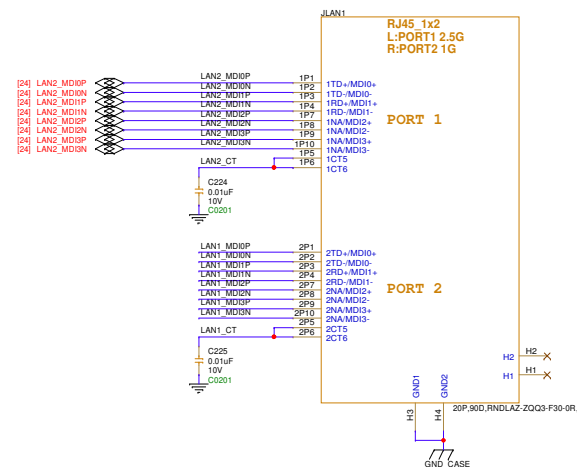
LEDs	Mode	Function
LED0	0100	LINK/ACTIVITY
LED1	0111	LINK 1000
LED2	0110	LINK 100

SMBus Device Addresses



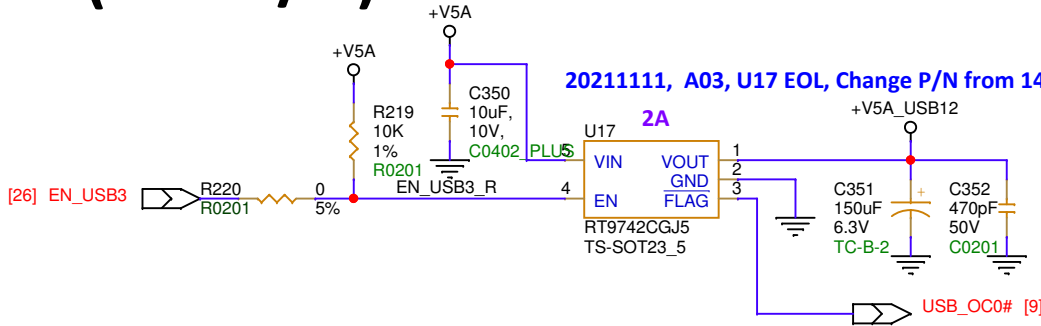
20211103, A03,
1. Change P/N of Y3 from 12310025A5 to 12310025AE
2. Change value of C330 and C331 from 15pF to 12pF, by FAE test result.

20211220, A03, Change P/N of Y3 from 12310025AE to 12310025A5 by buver Tina issue.



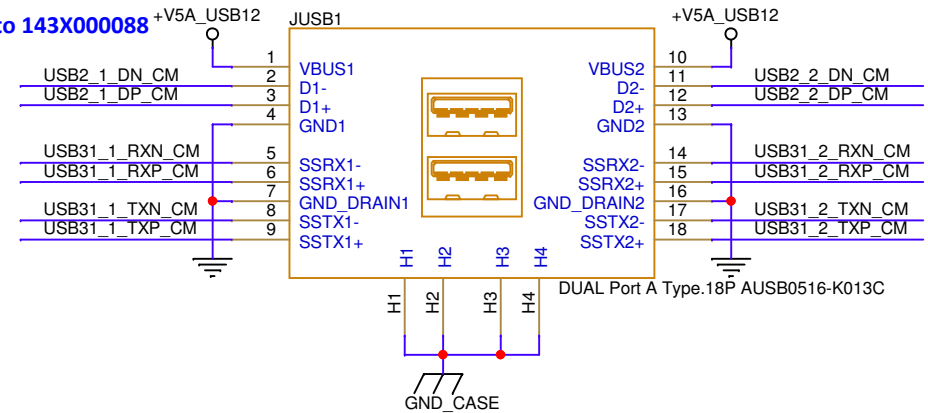
<Variant Name>

USB3 (Rear I/O)



USB3 *2(Rear I/O)

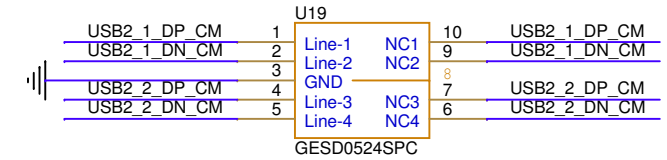
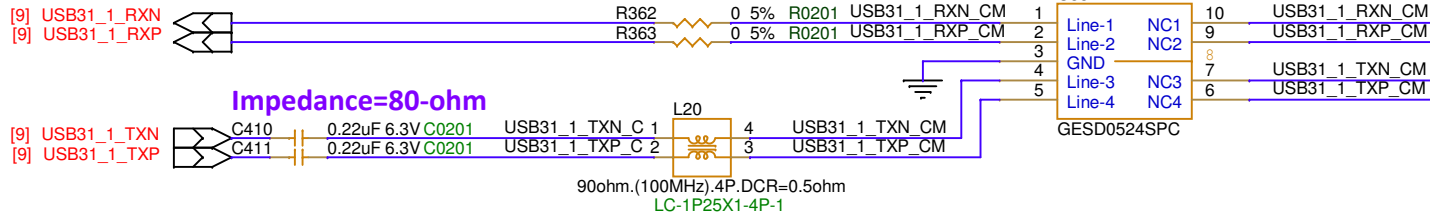
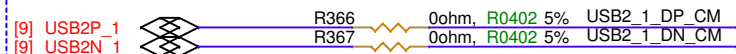
USB3.1 GEN2



USB3 PORT 1

20210519, A02, Change USB3 port1/2 to PCH HSIO port 3/4

20211014, A03, Change L7 to 0R resistor for SI issue

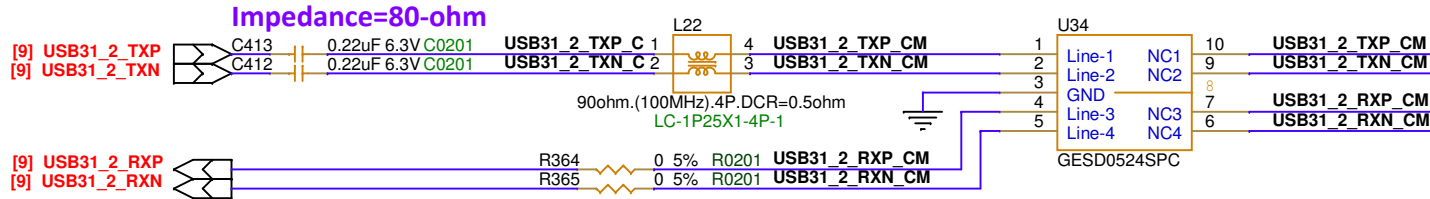
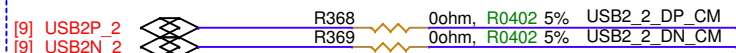


20210601, A02, Change P/N of U19, U33, U34 from 130505ESD0 to 13055V0SP0 for EOL

20211111, A03, U19, U33, U34 EOL, Change P/N from 13055V0SP0 to 1305Q00022

USB3 PORT 2

20211014, A03, Change L9 to 0R resistor for SI issue



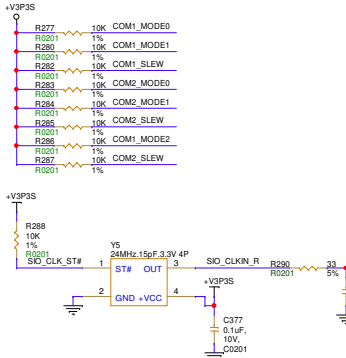
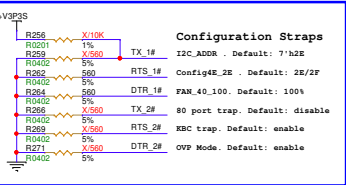
<Core Design>



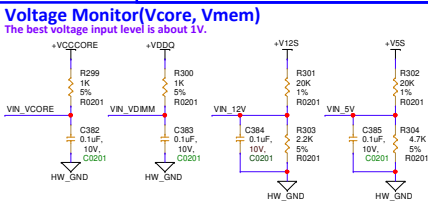
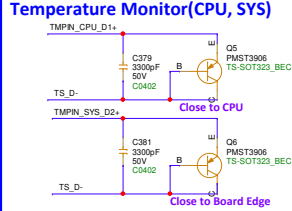
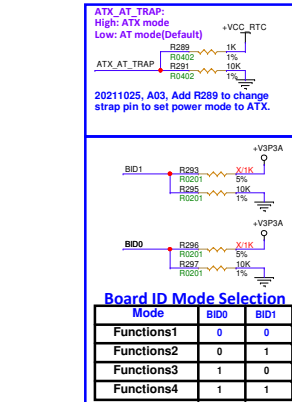
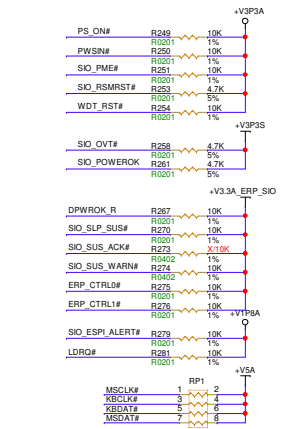
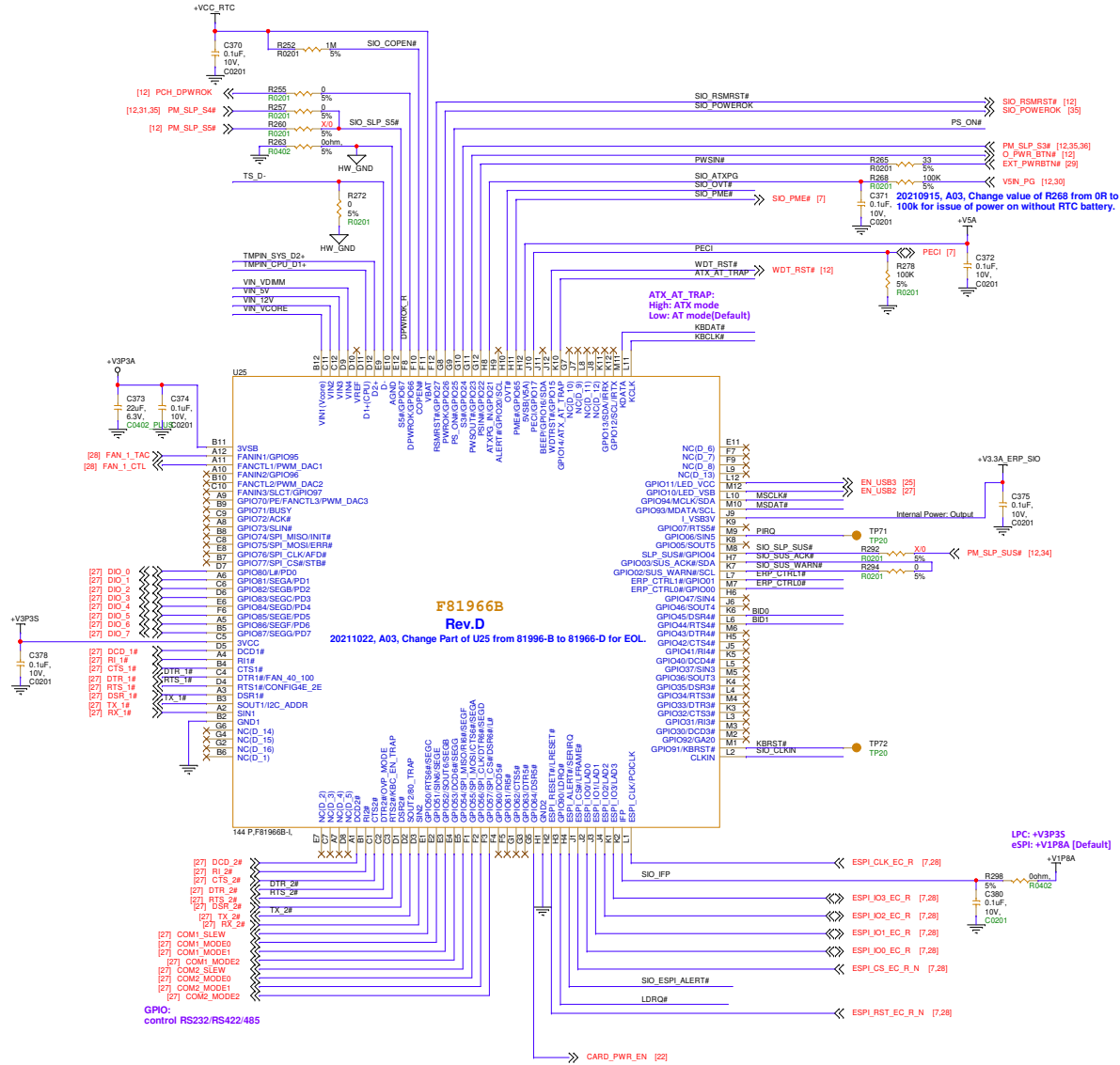
AAEON Technology INC.

Title			USB3.1		
Size	Document Number		Rev		
A4	DN-TGU8		A0.3_0_0		
Date:	Tuesday, January 04, 2022		Sheet	25	of 37

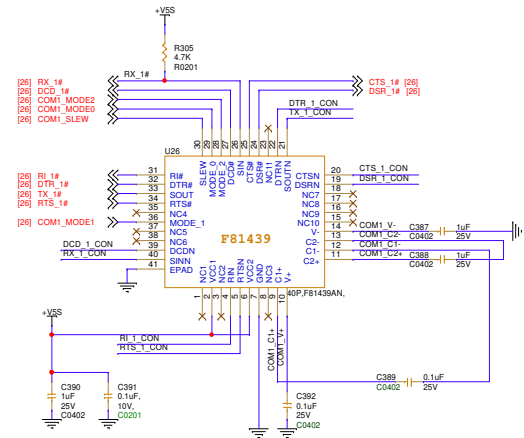
Super I/O F81966



Power On Strapping Options pin	
JP4, PIN 126	I2C_ADDR
HIGH	The I2C slave address is 0X5C (Default)
LOW	The I2C slave address is 0X5A
JP3, PIN 124	Config4E_2E
HIGH	Configuration Register I/O port is 4E/4F
LOW	Configuration Register I/O port is 2E/2F (Default)
JP2, PIN 123	FAN40_100
HIGH	Power on fan speed default duty is 40% (Default)
LOW	Power on fan speed default duty is 100%
JP1, PIN 4	OVP_Mode
HIGH	(ALARM mode) Disable OVP function
LOW	(FORCE mode) Enable OVP function



COM1-RS232/RS422/RS485 F81439 is for RS232/422/485

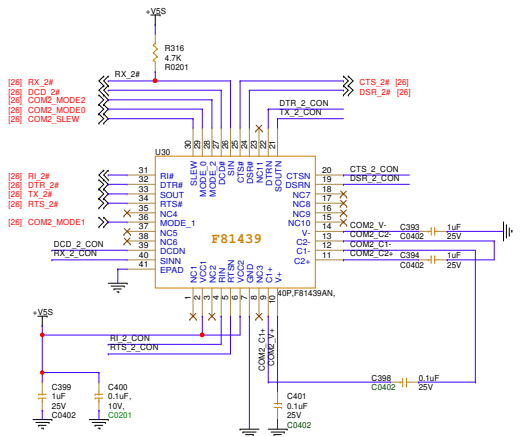


SLEW	RS233	RS422/RS485
1	250kbps	250kbps
0	1Mbps	10Mbps

Serial Port 1 Mode Selection

Mode	MODE_0	MODE_1	MODE_2
RS-422	0	0	0
RS-232	0	0	1
RS-485 (Driver Half Duplex)	0	1	0
RS-485 (Receiver Half Duplex)	0	1	1
Shutdown MODE	1	X	X

COM2-RS232/RS422/RS485

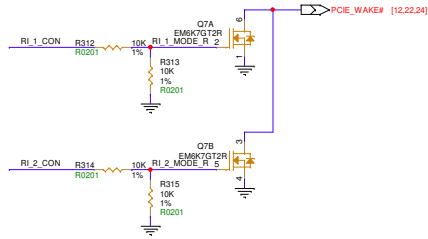


SLEW	RS233	RS422/RS485
1	250kbps	250kbps
0	1Mbps	10Mbps

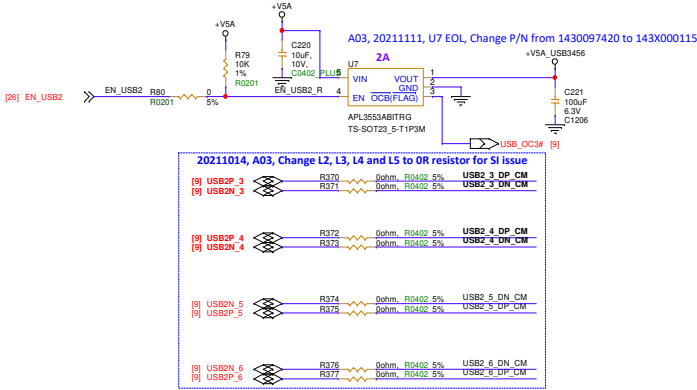
Serial Port 1 Mode Selection

Mode	MODE_0	MODE_1	MODE_2
RS-422	0	0	0
RS-232	0	0	1
RS-485 (Driver Half Duplex)	0	1	0
RS-485 (Receiver Half Duplex)	0	1	1
Shutdown MODE	1	X	X

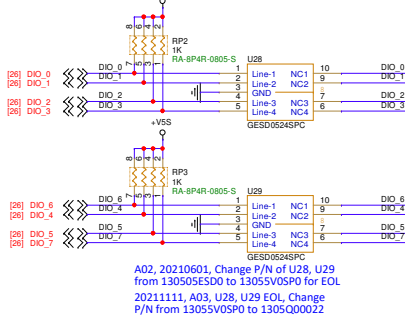
Wake on Modem



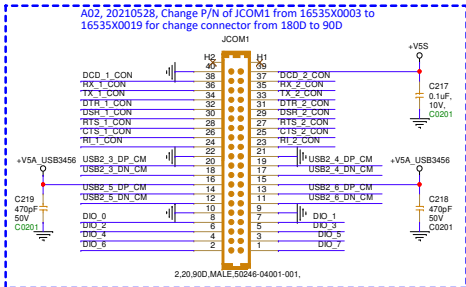
USB2.0 *4 (Pin Header)



DIO 8BITS



PIN	RS422	RS485	DB-9 Con.
7	DCD1	TX1-	DATA1-
9	RX1	TX1+	DATA1+
11	TX1	RX1+	COM1_3
13	DTR1	RX1-	COM1_4
15	DSR1		COM1_6
17	RTS1		COM1_7
19	CTS1		COM1_8
21	RI1		COM1_9
8	DCD2	TX2-	DATA2-
10	RX2	TX2+	DATA2+
12	TX2	RX2+	COM2_3
14	DTR2	RX2-	COM2_4
16	DSR2		COM2_6
18	RTS2		COM2_7
20	CTS2		COM2_8
22	RI2		COM2_9



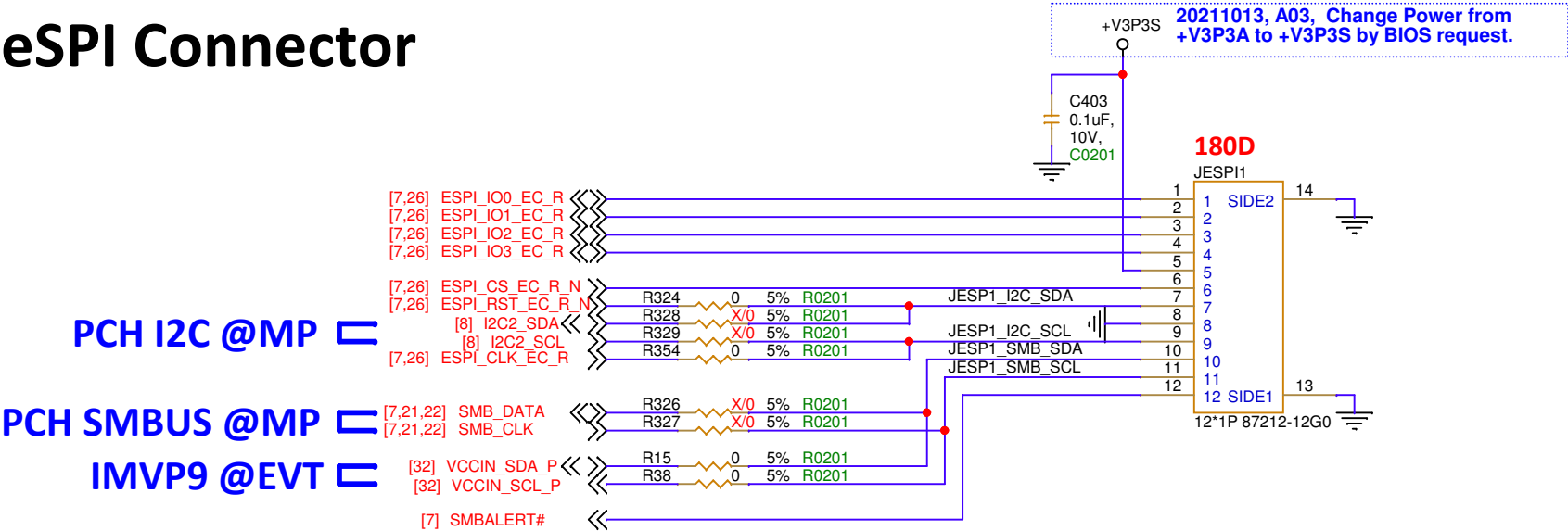
PIN	RS422	RS485	DB-9 Con.
7	DCD1	TX1-	DATA1-
9	RX1	TX1+	DATA1+
11	TX1	RX1+	COM1_3
13	DTR1	RX1-	COM1_4
15	DSR1		COM1_6
17	RTS1		COM1_7
19	CTS1		COM1_8
21	RI1		COM1_9
8	DCD2	TX2-	DATA2-
10	RX2	TX2+	DATA2+
12	TX2	RX2+	COM2_3
14	DTR2	RX2-	COM2_4
16	DSR2		COM2_6
18	RTS2		COM2_7
20	CTS2		COM2_8
22	RI2		COM2_9

A02_20210528, Change P/N of JCOM1 from 16535X0003 to 16535X0019 for change connector from 180D to 90D

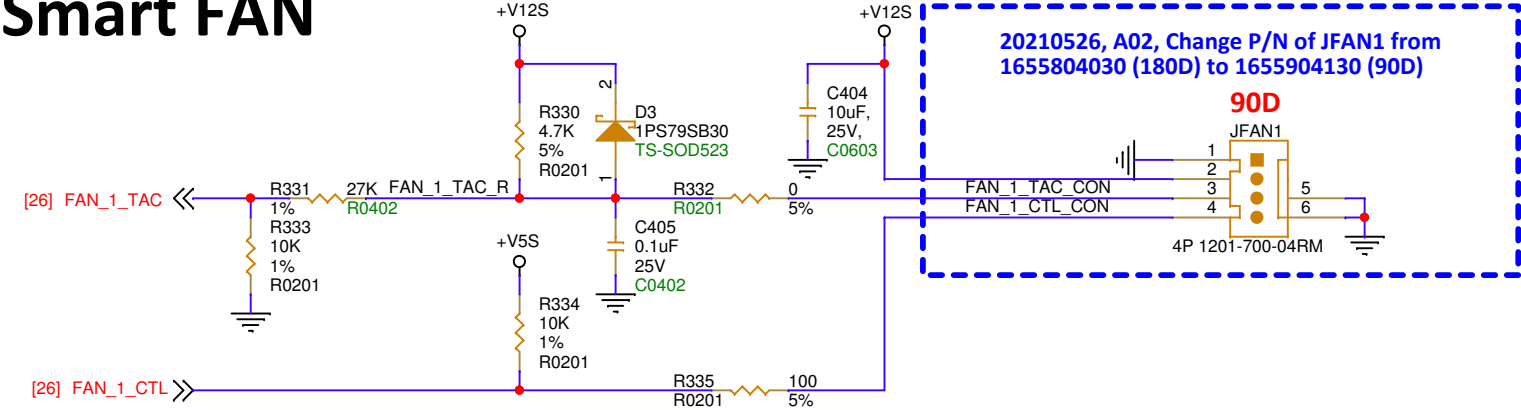
A02_20210601, Change P/N of U13, U27 from 130505ESD0 to 13055V0SP0 for EOL

20211111, A03, U13, U27 EOL, Change P/N from 13055V0SP0 to 1305Q00022

eSPI Connector

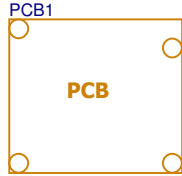


Smart FAN



PCB

20210520, A02, Update P/N of PCB1 from 1907TGU800 to 1907TGU801

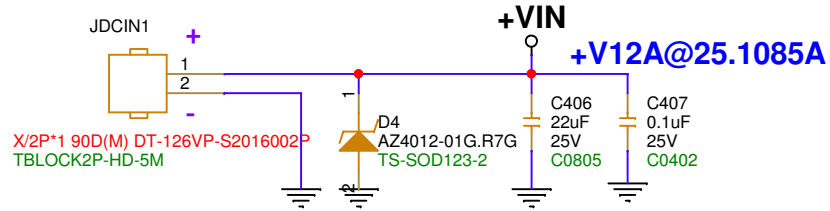


PCB.DN-TGU8.Rev.A0.3_0_0.HDI.(2+12+2).16Layers.Matt Black.1*2.84*55*2.0mm

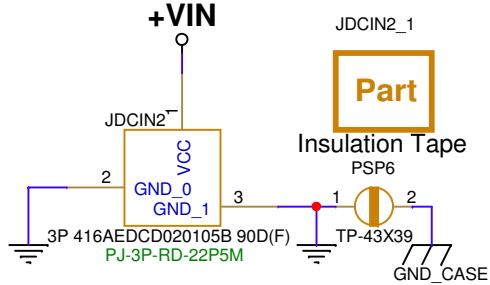
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AAEON Technology INC.			
Title			
SMBus/I2C/FAN			
Size	Document Number		Rev
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Date:	Tuesday, January 04, 2022	Sheet	28 of 37

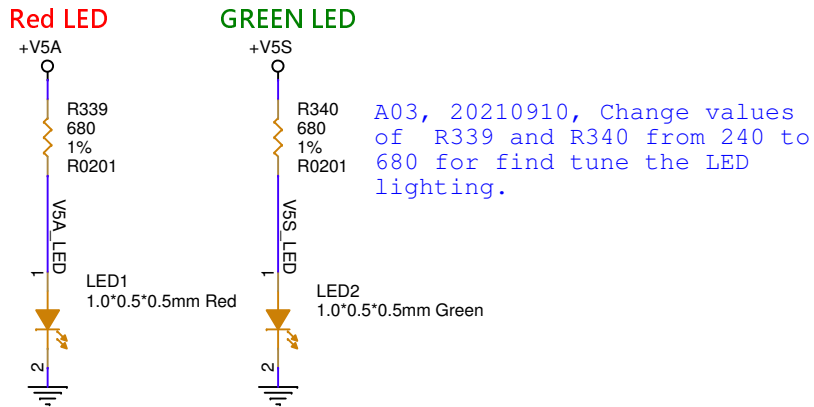
Power Input 12V



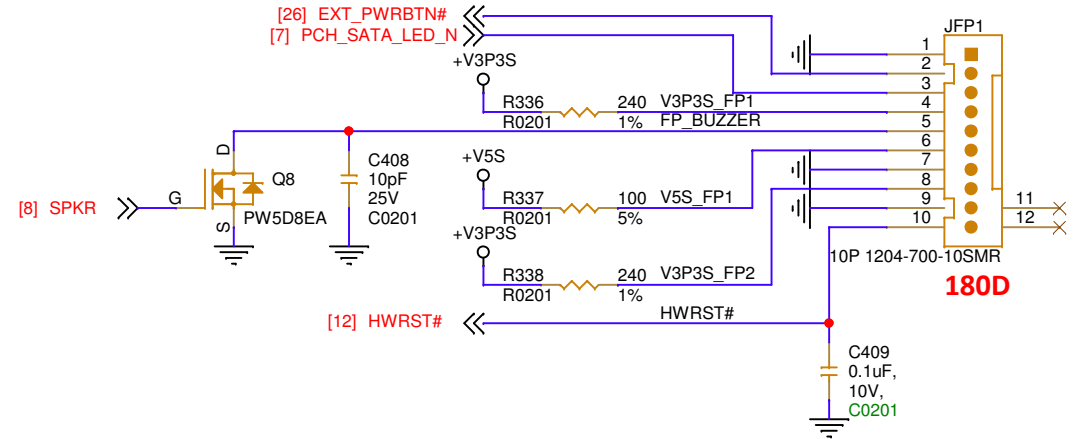
DC Jack (JDCIN2 Colay JDCIN1)



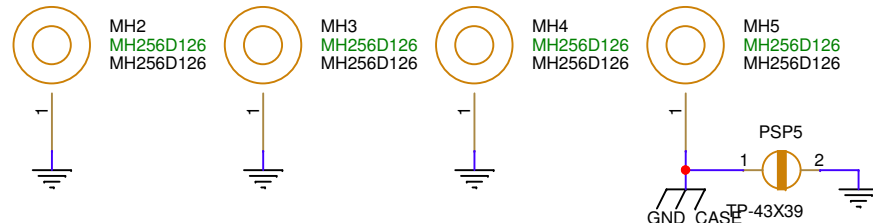
LED



Front Panel



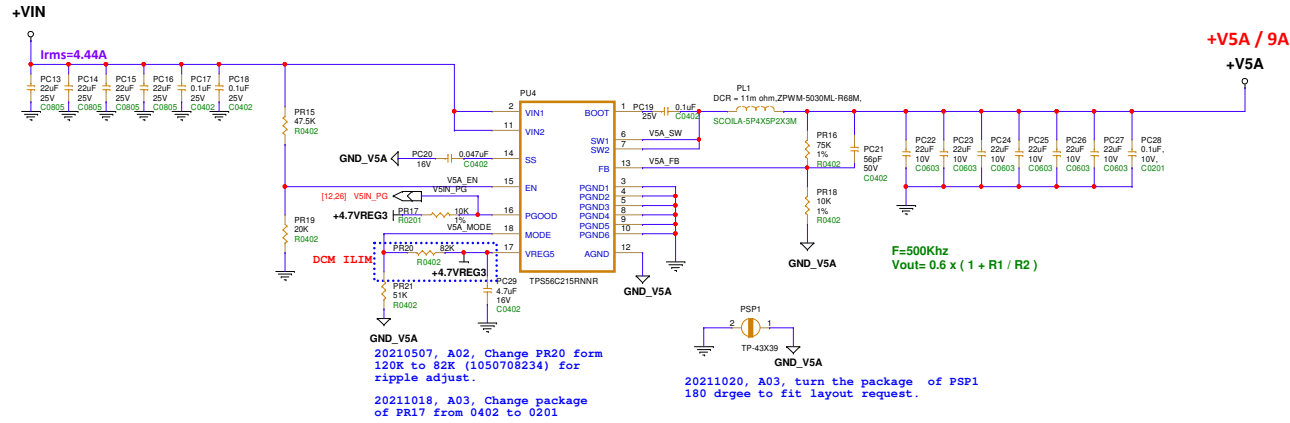
Mounting Holes / Non-PTH



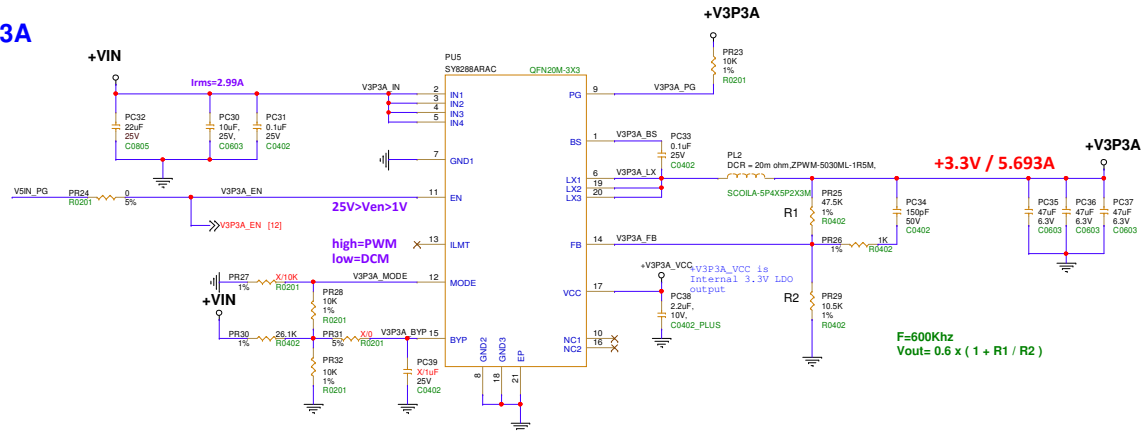
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AAEON Technology INC.			
Title			
DC IN/MISC			
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A4	DN-TGU8		A0.3_0_0
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+V5A



+V3P3A

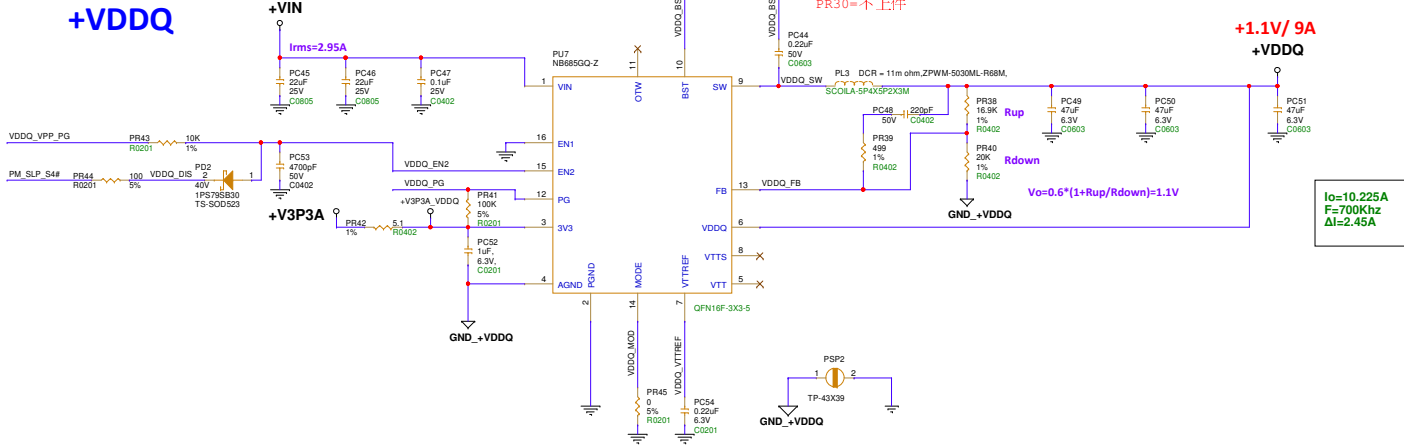
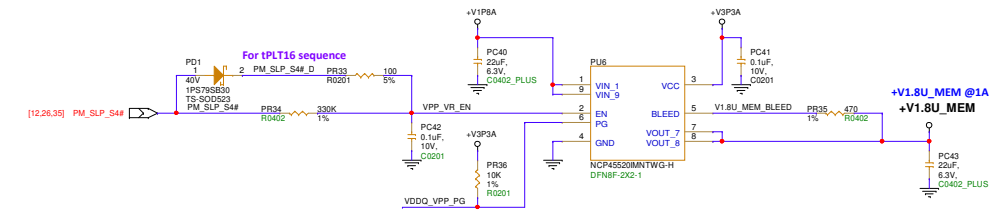


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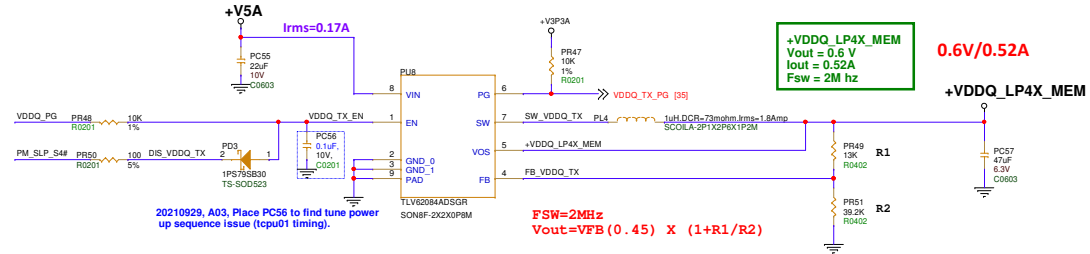
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POWER_+V5S_+V3P3A		A0.3_0_0
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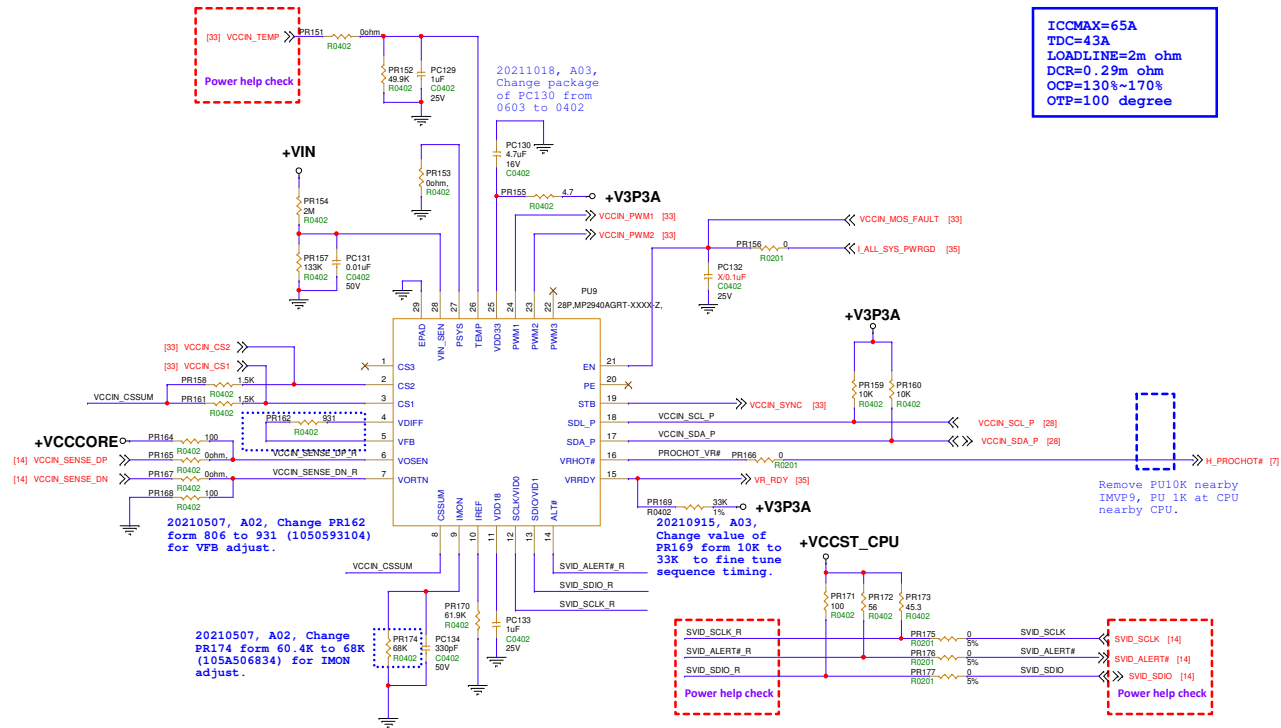
+V1.8U_MEM



+VDDQ_LP4X_MEM



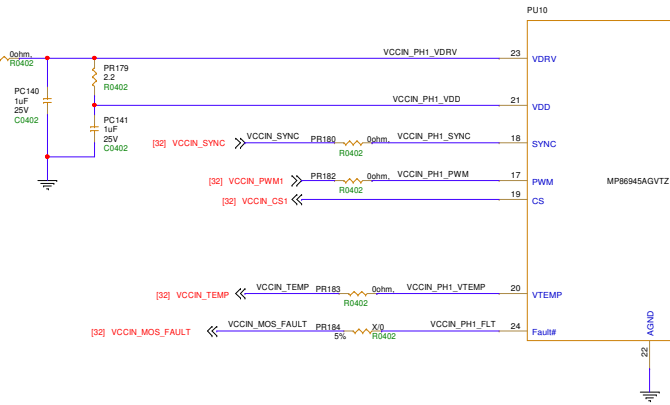
Tiger Lake IMVP9



+VCCCORE

A02, 20210407, Modify the circuit from +V5A to +V3P3A for sequence issue.

+V3P3A



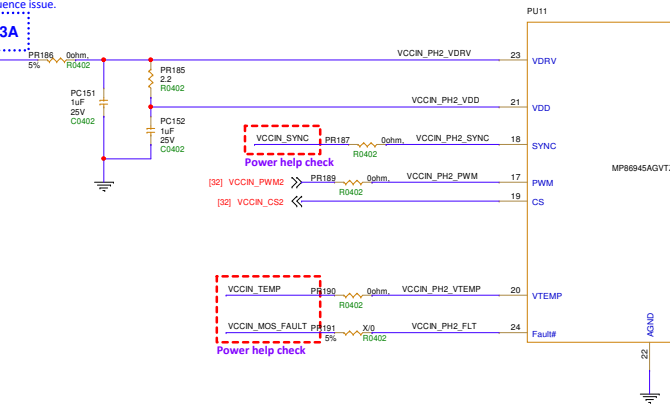
+VIN

max=65A

+VCCCORE

A02, 20210407, Modify the circuit from +V5A to +V3P3A for sequence issue.

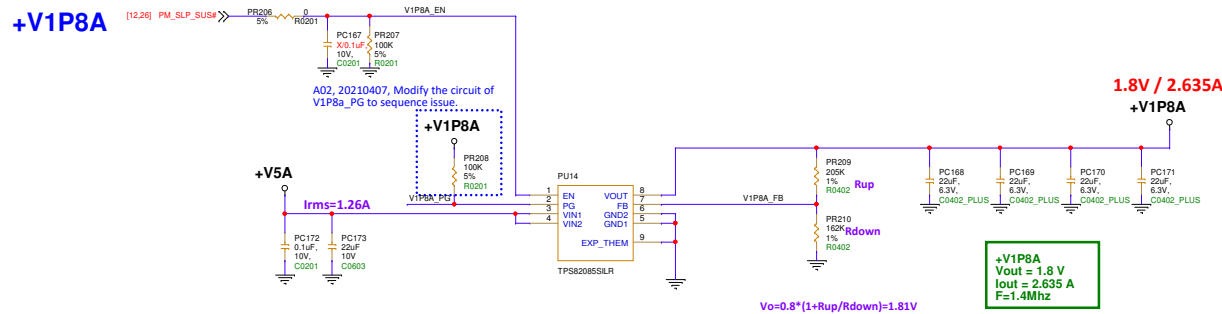
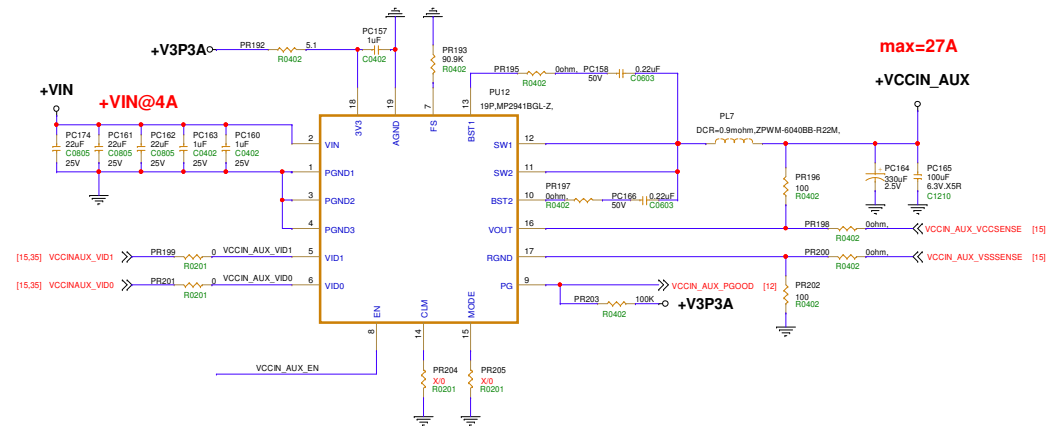
+V3P3A



+VIN

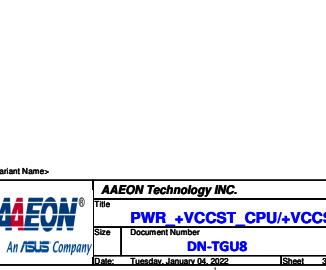
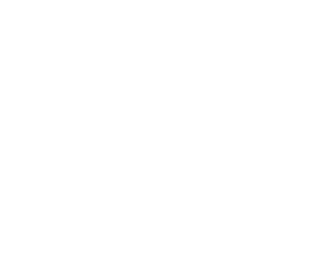
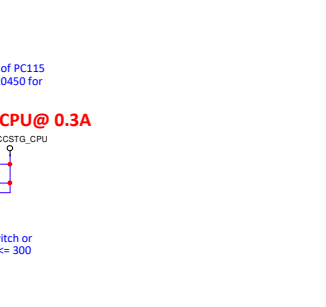
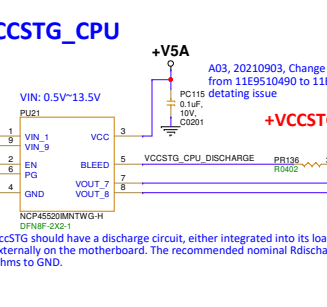
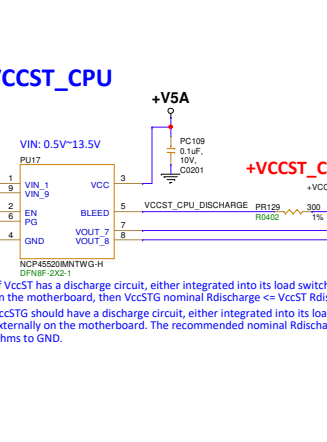
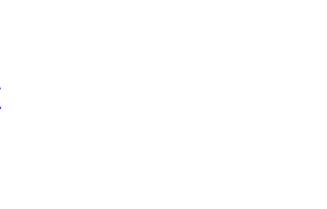
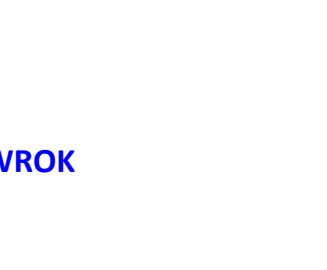
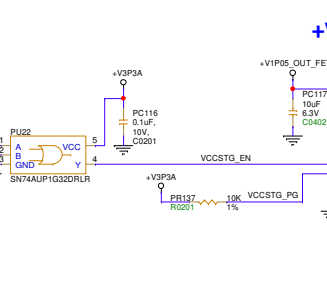
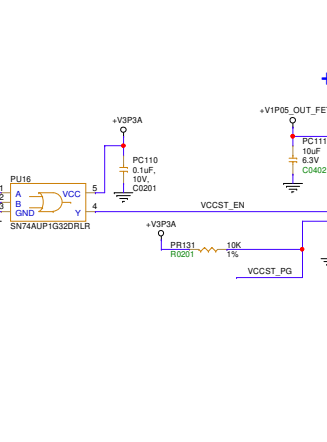
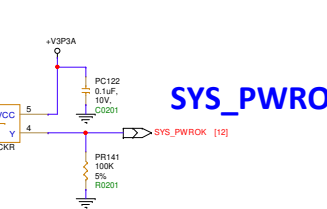
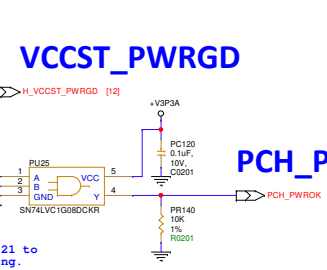
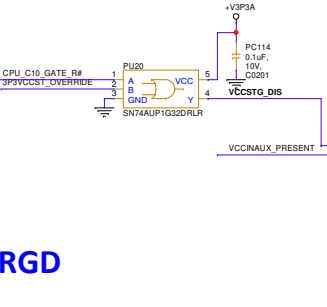
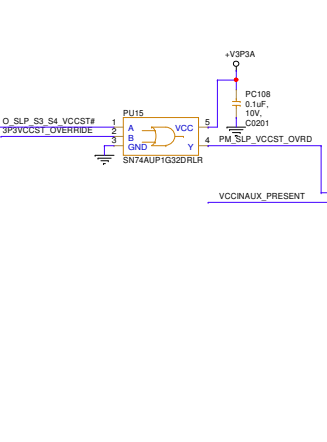
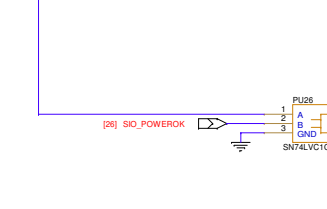
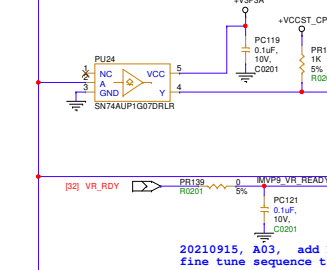
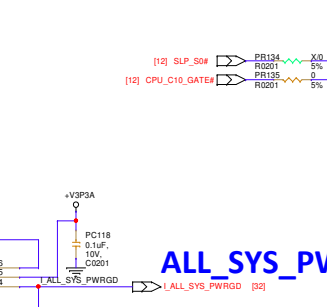
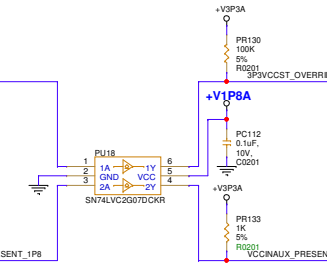
+VCCCORE

VID1	VID0	VCCIO
0	0	0V
0	1	1.1V
1	0	1.65V
1	1	1.8V



#632415
C330due to improper initialization of logic on the VCCST power domain in the Tiger Lake-UP3, the system may fail to exit S3.
Workaround: Intel recommends a rework of the platform by keeping the VCCST enabled during S3. Unmount P92 + mount PR155.

A03, 20210901, Remove PR128 and place PR126 for Tiger lake resume from G3 issue.



+VCCST_CPU

+V5A

+VCCST_CPU@0.5A

If VccST has a discharge circuit, either integrated into its load switch or externally on the motherboard, then VccSTG nominal Rdischarge <= VccST Rdischarge.
VccSTG should have a discharge circuit, either integrated into its load switch or externally on the motherboard. The recommended nominal Rdischarge <= 300 Ohms to GND.

+VCCSTG_CPU

+V5A

+VCCSTG_CPU@ 0.3A

A03, 20210903, Change P/N of PC115 from 11E9510490 to 11E8510450 for detaching issue

VccSTG should have a discharge circuit, either integrated into its load switch or externally on the motherboard. The recommended nominal Rdischarge <= 300 Ohms to GND.

ALL_SYS_PWRGD

VCCST_PWRGD

PCH_PWROK

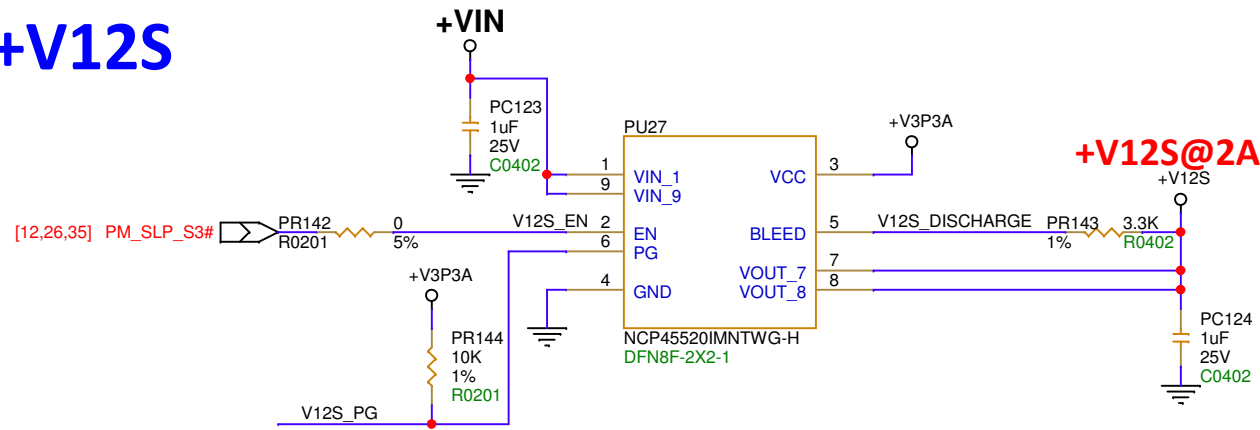
SYS_PWROK

20210915, A03, add PC121 to fine tune sequence timing.

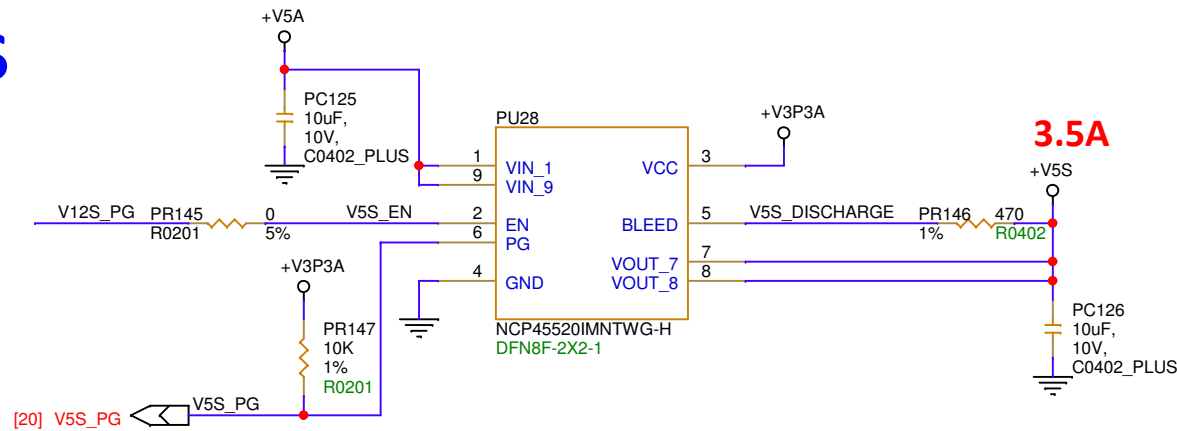
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AAEON Technology INC.			
Title		PWR +VCCST_CPU+VCCSTG_CPU	
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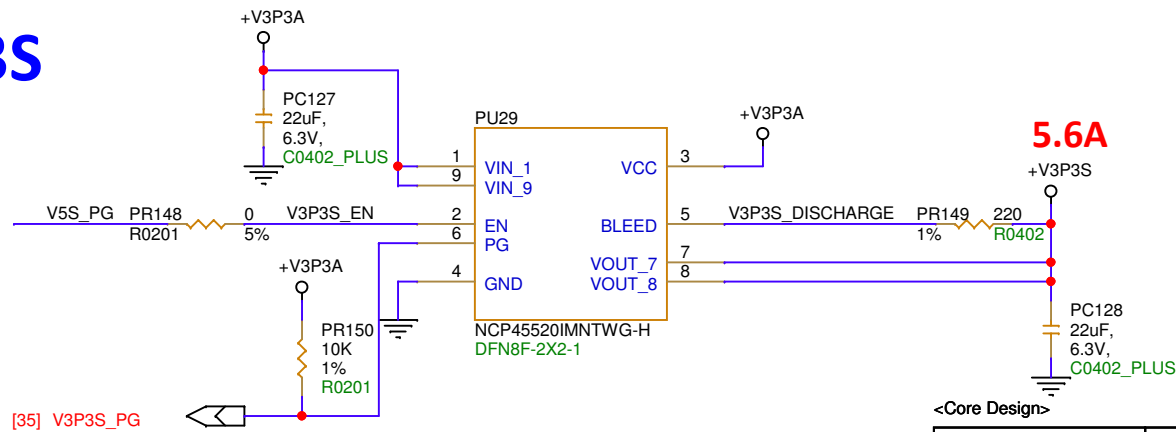
+V12S



+V5S



+V3P3S



<Core Design>



AAEON Technology INC.

Title			PWR_+V12S/ +V5S/ +V3P3S	
Size	Document Number	Rev		
A4	DN-TGU8	A0.3_0_0		
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DN-TGU8 Revision History

01. Project code: E201009
02. Model name: DN-TU G8
03. Model revision: A0.3_0_0
04. 96-Level: 9697TGU808~
05. PCB 料號: 1907TGU802
06. PCB 厚度: 2.0 mm
07. PCB 層數: 16 Layer
08. 連板數量: 2 pcs
09. PCB VIA: HDI/2+12+2
10. Material: TU-883
11. PCB Dimension: 86x55mm

DN-TGU8 A0.1_0_0 PCB: 1907TGU800 BOM: 9697TGU800~9697TGU803 Date: 2020/12/16 (TF)PCB.DN-TGU8.Rev.A0.1_0_0.HDI.(2+N+2).16L.GREEN.1*2.84*55mm
DN-TGU8 A0.2_0_0 PCB: 1907TGU801 BOM: 9697TGU804~9697TGU807 Date: 2021/05/20 (TF)PCB.DN-TGU8.Rev.A0.2_0_0.HDI.(2+12+2).16Layers.Green.1*2.84*55*2.0mm
DN-TGU8 A0.3_0_0 PCB: 1907TGU802 BOM: 9697TGU808~9697TGU80B Date: 2021/12/13 (TF)PCB.DN-TGU8.Rev.A0.3_0_0.HDI.(2+12+2).16Layers.Matt Black.1*2.84*55*2.0mm

(TF)SMD ASS'Y.DN-TGU8Rev.A0.3_0_0.INTEL Tigerlake-UP3		
BOM NUMBER	CPU	P/N
9697TGU808	i7-1185G7E	1441185G70
9697TGU809	i5-1145G7E	1441145G70
9697TGU80A	i3-1115G4E	1441115G40
9697TGU80B	i3-1115GRE	144X000096

Revision HistoryPage 1

Item	Page #	Title	Date	Request Owner	Issue Description	Solution Description	Rev.	Bug ID
1	5, 9, 22, 25	USB3	20210519	HW	Intel TCP doesn't support USB3 TYPE A	Change USB3.2 Port 1/2 from TCP to PCH HSIO	A02	
2	8	I2C	20200717	HW	Request of BIOS for test.	Add TP30~TP33 for BIOS request	A02	
3	8	Strap	20210407	HW	Issue of ME disable because the level isn't low enough at the strap pin.	Add R361 and remove TP13 for intel ME disable issue.	A02	
4	30	Power	20210507	Power	Power ripple adjust.	Change PR20 form 120K to 82K (1050708234) for ripple adjust.	A02	
5	32	Power	20210507	Power	Power VFB adjust.	Change PR162 form 806 to 931 (1050593104) for VFB adjust.	A02	
6	32	Power	20210507	Power	Power IMON adjust.	Change PR174 form 60.4K to 68K (105A506834) for IMON adjust.	A02	
7	33	Power	20210407	Power	Power sequence issue	Modify the circuit from +V5A to +V3P3A for sequence issue	A02	
8	07	SPI	20210831	HW	Remove JP1 for PE request.	Remove JP1	A03	
9	10	RTC	20210831	HW	Change P/N of JRTC1 from 1655902034 to 1655X00019 by PE suggestion	Change P/N of JRTC1 from 1655902034 to 1655X00019	A03	
10	12, 30	SEQUENCE	20210929	HW	tPCH14 timing fail	1. ADD D5 2. Change package of PR17 from 0402 to 0201 3. turn the package of PSP1 180 drgee to fit layout Request	A03	
11	21	PCIE	20211025	HW	1654904032 EOL	Change P/N of JPCIE_FPC1 from 1654904032 to 1654904035	A03	
12	25, 27	USB	20211014	HW	USB 2.0 SI fail	Change L7, L9, L2~L5 to 0R resistor	A03	
13	26	SIO	20210915	HW	power on without RTC battery fail	Change value of R268 from 0R to 100k	A03	
14	26	SIO	20211022	HW	81996-B EOL	Change Part of U25 from 81996-B to 81966-D	A03	
15	26	SIO	20211025	HW	Change strap pin to set power mode to ATX.	ADD R289	A03	
16	28	eSPI	20211013	HW	Change Power from +V3P3A to +V3P3S by BIOS request.	Change Power at JESPI.5 from +V3P3A to +V3P3S	A03	
17	29	LED	20210910	HW	find tune the LED lighting	Change values of R339 and R340 from 240 to 680	A03	
18	31	SEQUENCE	20210929	HW	topu01 timing fail	Place PC56 to find tune power up sequence issue	A03	
19	32	SEQUENCE	20210915	HW	fine tune sequence timing	Change value of PR169 form 10K to 33K	A03	
20	32	POWER	20211018	HW	Change package of PC130 from 0603 to 0402	Change package of PC130 from 0603 to 0402	A03	
21	35	POWER	20210901	HW	Tiger lake resume from G3 issue.	Remove PR128 and place PR126	A03	
22	35	POWER	20210903	HW	detating issue	Change P/N of PC115 from 11E9510490 to 11EB510450	A03	
23	35	SEQUENCE	20210915	HW	fine tune sequence timing	add PC121	A03	
24	24	I225	20211103	HW	Fine tune xtal frequence by FAE test result	1. Change P/N of Y7 from 12310025A5 to 12310025AE 2. Change value of C306 and C324 from 10pF to 6.2pF, by FAE test result.	A03	
25	10	Xtal	20211027	HW	change vendor	Change P/N Y1 from 1231327631 to 1231332726	A03	
26	23	LAN	20211103	HW	Fine tune xtal frequence by FAE test result	1. Change P/N of Y3 from 12310025A5 to 12310025AE 2. Change value of C330 and C331 from 15pF to 12pF, by FAE test result.	A03	
27	20, 25, 27	TVR	20211111	HW	13055V0SP0 EOL	Change P/N from 13055V0SP0 to 1305Q00022 for U22~U24, U19, U33, U34, U13, U27, U28, U29	A03	
28	27	USB	20211111	HW	1430097420 EOL	U7 EOL, Change P/N from 1430097420 to 143X000115	A03	
29	21	PCIE	20211111	HW	JPCIE_FPC1 EOL	Change P/N of JPCIE_FPC1 from 1654904035 to 16549X0027	A03	
30	25	USB	20211111	HW	U17 EOL	Change P/N from 1430097420 to 143X000088	A03	
31	22	M.2	20211115	HW	to enable 4G/5G WWAN card	Place R360	A03	